

Rockchip

RK3399

Datasheet

Revision 2.0
Oct. 2019

Revision History

Date	Revision	Description
2019-10-10	2.0	● Add some feature
2018-10-30	1.9	● Update the description of OpenGL ES
2018-5-29	1.8	● Add RK3399K information
2017-6-1	1.7	● Updated the description about "power supply for IO"
2017-3-1	1.6	● Update
2016-12-20	1.5	● Update "Recommended Operating Conditions" for CPU A72
2016-12-06	1.4	● Removed repeated "EMMC_COREDLL_0V9" in section 3.2 ● Add ball description for "EMMC_COREDLL_0V9" in section 2.6
2016-10-30	1.3	● Updated ball description for DDR1 in section 2.6
2016-9-30	1.2	● Update the description about video codec
2016-8-15	1.1	● Updated I2C information about Fast-mode plus feature ● Updated video codec about H264/H265/VP9 ● Updated voltage information for power supply ● Updated PCIe specification ● Updated "Features" section
2016-5-04	1.0	● Initial Release

Table of Content

Table of Content	3
Figure Index	5
Table Index 6	
Chapter 1 Introduction	8
1.1 Overview.....	8
1.2 Features.....	8
1.3 Block Diagram	26
Chapter 2 Package information	27
2.1 Ordering information	27
2.2 Top Marking.....	27
2.3 Dimension	28
2.4 Ball Map.....	30
2.5 Ball Pin Number Order	37
2.6 Power/ground IO descriptions	47
2.7 Power supply for IO	49
2.8 Function IO description	52
2.9 IO pin name descriptions.....	57
Chapter 3 Electrical Specification	65
3.1 Absolute Maximum Ratings.....	65
3.2 Recommended Operating Conditions.....	65
3.3 DC Characteristics	67
3.4 Electrical Characteristics for General IO.....	68
3.5 Electrical Characteristics for PLL	69
3.6 Electrical Characteristics for SAR-ADC	69
3.7 Electrical Characteristics for TSADC	70
3.8 Electrical Characteristics for Type-C PHY.....	70
3.9 Electrical Characteristics for USB2.0 PHY	70
3.10 Electrical Characteristics for DDR IO	71
3.11 Electrical Characteristics for eFuse	71
3.12 Electrical Characteristics for HDMI	71
3.13 Electrical Characteristics for MIPI PHY	72
3.14 Electrical Characteristics for eMMC PHY	72
3.15 Electrical Characteristics for PCIe PHY	73

Chapter 4 Thermal Management	75
4.1 Overview	75
4.2 Package Thermal Characteristics	75

Figure Index

Fig. 1-1 Block Diagram	26
Fig. 2-1 Top Marking	27
Fig. 2-2 Package Top and SideView	28
Fig. 2-3 Package Bottom View	28
Fig. 2-4 Package Dimension	29
Fig. 2-5 Ball Mapping Diagram.....	30

Table Index

Table 2-1 Ball Pin Number Order Information	37
Table 2-2 Power/Ground IO information	47
Table 2-3 Function IO description	52
Table 2-4 eMMC pin description	57
Table 2-5 PCIe pin description	57
Table 2-6 USB2 pin description	57
Table 2-7 eDP pin description	58
Table 2-8 HDMI pin description	58
Table 2-9 MIPI pin description	59
Table 2-10 ISP pin description	59
Table 2-11 EFUSE pin description	60
Table 2-12 SAR-ADC pin description	60
Table 2-13 TSADC pin description	60
Table 2-14 GMAC pin description.....	60
Table 2-15 UART pin description.....	60
Table 2-16 I2C pin description	60
Table 2-17 PWM pin description	61
Table 2-18 CIF pin description	61
Table 2-19 SPI pin description	61
Table 2-20 SPDIF pin description.....	61
Table 2-21 I2S pin description	62
Table 2-22 DDRC pin description.....	62
Table 2-23 SDIO pin description.....	63
Table 2-24 SDMMC pin description	63
Table 2-25 JTAG pin description	63
Table 2-26 MISC pin description.....	64
Table 3-1 Absolute maximum ratings.....	65
Table 3-2 Recommended operating conditions.....	65
Table 3-3 DC Characteristics.....	67
Table 3-4 Electrical Characteristics for Digital General IO	68
Table 3-5 Electrical Characteristics for PLL.....	69
Table 3-6 Electrical Characteristics for SAR-ADC	69
Table 3-7 Electrical Characteristics for TSADC	70
Table 3-8 Electrical Characteristics for Type-C PHY.....	70
Table 3-9 Electrical Characteristics for USB2.0 PHY	70
Table 3-10 Electrical Characteristics for DDR IO	71
Table 3-11 Electrical Characteristics for eFuse	71
Table 3-12 Electrical Characteristics for HDMI	71
Table 3-13 Electrical Characteristics for MIPI PHY	72
Table 3-14 Electrical Characteristics for eMMC PHY	72
Table 3-15 Electrical Characteristics for PCIe PHY	73
Table 4-1 Thermal Resistance Characteristics.....	75

NOTICE

Copyright © 2017, Fuzhou Rockchip Electronics Co., Ltd. All rights reserved.

1. By using this document, you hereby unequivocally acknowledge that you have read and agreed to be bound by the contents of this notice.

2. Fuzhou Rockchip Electronics Co., Ltd. ("Rockchip") may make changes to any information in this document at any time without any prior notice. The information herein is subject to change without notice. Do not finalize a design with this information.

3. Information in this document is provided in connection with Rockchip products.

4. THIS DOCUMENT IS PROVIDED "AS IS" WITHOUT ANY WARRANTY OR CONDITION OF ANY KIND, EITHER EXPRESS, IMPLIED OR STATUTORY, INCLUDING, WITHOUT LIMITATION, ANY WARRANTY OR CONDITION WITH RESPECT TO MERCHANTABILITY, FITNESS FOR ANY PARTICULAR PURPOSE, OR NON-INFRINGEMENT. ROCKCHIP DOES NOT ASSUME ANY RESPONSIBILITY AND LIABILITY FOR ITS USE NOR FOR ANY INFRINGEMENT OF PATENTS OR OTHER RIGHTS OF THE THIRD PARTIES WHICH MAY RESULT FROM ITS USE.

5. Rockchip products described in this document are not designed, intended for use in medical, lifesaving, life sustaining, critical control or safety systems, or in nuclear facility application.

6. Rockchip and Rockchip logo are trademarks or registered trademarks of Rockchip in China and other countries. All referenced brands, product names, service names and trademarks in this document are the property by their respective owners.

Chapter 1 Introduction

1.1 Overview

RK3399 is a low power, high performance processor for computing, personal mobile internet devices and other smart device applications. Based on Big.Little architecture, it integrates dual-core Cortex-A72 and quad-core Cortex-A53 with separate NEON coprocessor.

Many embedded powerful hardware engines provide optimized performance for high-end application. RK3399 supports multi-format video decoders including H.264/H.265/VP9 up to 4Kx2K@60fps, especially, H.264/H.265 decoders support 10bits coding, and also supports H.264/MVC/VP8 encoders by 1080p@30fps, high-quality JPEG encoder/decoder, and special image preprocessor and postprocessor.

Embedded 3D GPU makes RK3399 completely compatible with OpenGL ES1.1/2.0/3.0/3.1/3.2, OpenCL 1.2 and DirectX 11.1. Special 2D hardware engine with MMU will maximize display performance and provide very smooth operation.

RK3399 has high-performance dual channel external memory interface (DDR3/DDR3L/LPDDR3/LPDDR4) capable of sustaining demanding memory bandwidths, also provides a complete set of peripheral interface to support very flexible applications.

1.2 Features

The features listed below which may or may not be present in actual product, may be subject to the third party licensing requirements. Please contact Rockchip for actual product feature configurations and licensing requirements.

1.2.1 Microprocessor

- Dual-core ARM Cortex-A72 MPCore processor and Quad-core ARM Cortex-A53 MPCore processor, both are high-performance, low-power and cached application processor
- Two CPU clusters. Big cluster with dual-core Cortex-A72 is optimized for high-performance and little cluster with quad-core Cortex-A53 is optimized for low power.
- Full implementation of the ARM architecture v8-A instruction set, ARM Neon Advanced SIMD (single instruction, multiple data) support for accelerating media and signal processing
- ARMv8 Cryptography Extensions
- SCU ensures memory coherency between the MPCore for each cluster
- CCI500 ensures the memory coherency between the two clusters
- Each Cortex-A72 integrates 48KB L1 instruction cache and 32KB L1 data cache with 4-way set associative. Each Cortex A53 integrates 32KB L1 instruction cache and 32KB L1 data cache separately with 4-way set associative
- 1MB unified L2 Cache for Big cluster, 512KB unified L2 Cache for Little cluster
- Trustzone technology support
- Full Coresight debug solution
 - Debug and trace visibility of whole systems
 - ETM trace support
 - Invasive and non-invasive debug
- Eight separate power domains for CPU core system to support internal power switch and externally turn on/off based on different application scenario
 - PD_A72_B0: 1st Cortex-A72 + Neon + FPU + L1 I/D cache of big cluster
 - PD_A72_B1: 2nd Cortex-A72 + Neon + FPU + L1 I/D cache of big cluster
 - PD_SCU_B: SCU + L2 Cache controller, and including PD_A72_B0, PD_A72_B1, debug logic of big cluster
 - PD_A53_L0: 1st Cortex-A53 + Neon + FPU + L1 I/D Cache of little cluster
 - PD_A53_L1: 2nd Cortex-A53 + Neon + FPU + L1 I/D Cache of little cluster
 - PD_A53_L2: 3rd Cortex-A53 + Neon + FPU + L1 I/D Cache of little cluster

- PD_A53_L3: 4th Cortex-A53 + Neon + FPU + L1 I/D Cache of little cluster
- PD_SCU_L: SCU + L2 Cache controller, and including PD_A53_L0, PD_A53_L1, PD_A53_L2, PD_A53_L3, debug logic of little cluster
- Two isolated voltage domain to support DVFS for big cluster and little cluster separately.

1.2.2 Memory Organization

- Internal on-chip memory
 - BootROM
 - Internal SRAM
- External off-chip memory^①
 - DDR3/DDR3L/LPDDR3/LPDDR4
 - SPI NOR/NAND Flash
 - eMMC 5.1
 - SD 3.0/MMC 4.51

1.2.3 Internal Memory

- Internal BootROM
 - Size : 32KB
 - Support system boot from the following device :
 - ◆ SPI interface
 - ◆ eMMC interface
 - ◆ SD/MMC interface
 - Support system code download by the following interface:
 - ◆ USB OTG interface
- Internal SRAM
 - Size : 200KB
 - Support security and non-security access
 - Security or non-security space is software programmable
 - Security space can be 0KB,4KB,8KB,12KB,16KB,... up to 64KB by 4KB step

1.2.4 External Memory or Storage device

- Dynamic Memory Interface (DDR3/DDR3L/LPDDR3/LPDDR4)
 - Compatible with JEDEC standard DDR3-1866/DDR3L-1866/LPDDR3-1866 / LPDDR4 SDRAM
 - Support 2 channels, each channel is 16 or 32bits data width
 - Support up to 2 ranks (chip selects) for each channel;totally 4GB(max) address space. Maximum address space of one rank in a channel is also 4GB, which is software-configurable
 - 32bits/64bits data width is software programmable
 - Programmable timing parameters to support DDR3/DDR3L/LPDDR3/LPDDR4 SDRAM from various vendor
 - Advanced command reordering and scheduling to maximize bus utilization
 - Embedded dynamic drift detection in the PHY to get dynamic drift compensation with the controller
 - Programmable output and ODT impedance with dynamic PVT compensation
 - Low power modes, such as power-down and self-refresh for DDR3/DDR3L/LPDDR3/LPDDR4 SDRAM
 - Support standby mode to auto-gating DDR controller clock for power save
 - Support power down DDR controller and DDR PHY
 - Support hardware-based DDR frequency scaling
- eMMC Interface
 - Fully compliant withJEDEC eMMC 5.1and eMMC 5.0 specification
 - There is only one eMMC interface
 - It is backward compliant with eMMC 4.51 and earlier versions specification.

- Supports HS400, HS200, DDR50 and legacy operating modes.
 - Provide eMMC boot sequence to receive boot data from external eMMC device
 - Configurable (Minimum 1 Block Size) FIFO used to aid data transfer between the CPU and the controller
 - Handle the FIFO overrun and underrun condition by stopping interface clock
 - Up to 3200Mbps per second data rate using 8 parallel data lines (eMMC HS400)
 - Up to 1600Mbps per second data rate using 8 parallel data lines (eMMC HS200)
 - Up to 832Mbps per second data rate using 8 parallel data lines (eMMC DDR52 mode)
 - Transfers the data in 1 bit, 4 bit and 8 bit modes
 - Cyclic Redundancy Check CRC7 for command and CRC16 for data integrity
- SD/MMC Interface
 - Compatible with SD3.0, MMC ver4.51
 - There are 2 MMC interfaces which can be configured as SD/MMC or SDIO
 - Support FIFO over-run and under-run prevention by stopping card clock automatically
 - Support CRC generation and error detection
 - Embedded clock frequency division control to provide programmable baud rate
 - Support block size from 1 to 65535Bytes
 - Data bus width is 4bits

1.2.5 System Component

- Cortex-M0
 - Two Cortex-M0 inside RK3399 to cooperate with Cortex-A72/Cortex-A53
 - Thumb instruction set combines high code density with 32-bit performance
 - Integrated sleep modes for low power consumption
 - Fast code execution permits slower processor clock or increases sleep mode time
 - Deterministic, high-performance interrupt handling for time-critical applications
 - Serial Wire Debug reduces the number of pins required for debugging
- CRU (clock & reset unit)
 - Support clock gating control for individual components inside RK3399
 - One oscillator with 24MHz clock input and 8 embedded PLLs
 - Support global soft-reset control for whole SOC, also individual soft-reset for every components
- PMU (power management unit)
 - Multipleconfigurable work modes to save power by different frequency or automatic clock gating control or power domain on/off control
 - Lots of wakeup sources in different mode
 - 6 separate voltage domains
 - 30 separate power domains, which can be power up/down by software based on different application scenes
- Timer
 - 14 on-chip 64bits Timers in SoC with interrupt-based operation for non-secure application
 - 12 on-chip 64bits Timers in SoC with interrupt-based operation for secure application
 - Provide two operation modes: free-running and user-defined count
 - Support timer work state checkable
 - Fixed 24MHz clock input
- PWM
 - Four on-chip PWMs with interrupt-based operation
 - Programmable pre-scaled operation to bus clock and then further scaled

- Embedded 32-bit timer/counter facility
- Support capture mode
- Support continuous mode or one-shot mode
- Provides reference mode and output various duty-cycle waveform
- Watchdog
 - Three Watchdogs in SoC with 32 bits counter width
 - Counter clock is from APB bus clock
 - Counter counts down from a preset value to 0 to indicate the occurrence of a timeout
 - WDT can perform two types of operations when timeout occurs:
 - ◆ Generate a system reset
 - ◆ First generate an interrupt and if this is not cleared by the service routine by the time a second timeout occurs then generate a system reset
 - Programmable reset pulse length
 - Totally 16 defined-ranges of main timeout period
- Mailbox
 - Two Mailboxes in SoC to service multi-core communication
 - Support four mailbox elements per mailbox, each element includes one data word, one command word register and one flag bit that can represent one interrupt
 - Provide 32 lock registers for software to use to indicate whether mailbox is occupied
- Bus Architecture
 - 128bit/64-bit/32-bit multi-layer AXI/AHB/APB composite bus architecture
 - CCI500 embedded to support two clusters cache coherency
 - 5 embedded AXI interconnect
 - ◆ PERI low performance interconnect with one 128-bits AXI master, seven 64-bits AXI masters, one 32-bits AXI master, two 64-bits AXI slaves, five 32-bits AHB masters and lots of 32-bits AHB/APB slaves
 - ◆ PERI high performance interconnect with one 128-bits AXI master, one 128-bits AXI slave, four 32-bits AHB masters and lots of 32-bits AHB/APB slaves
 - ◆ DISPLAY interconnect with two 128-bits AXI masters, two 64-bits AXI masters, one 32-bits AXI master and lots of 32-bits AHB/APB slaves
 - ◆ GPU interconnect with one 128-bits AXI master and 32-bits APB slave
 - ◆ VIDEO interconnect with two 128-bits AXI masters, two 64-bits AXI masters and four 32-bits AHB slaves
 - Flexible different QoS solution to improve the utility of bus bandwidth
- Interrupt Controller
 - Support 8 PPI interrupt source and 148 SPI interrupt sources input from different components inside RK3399
 - Support 16 software-triggered interrupts
 - Input interrupt level is fixed, high-level sensitive for SPI and low-level sensitive for PPI
 - Support Locality-specific Peripheral Interrupts (LPIs). These interrupts are generated by a peripheral writing to a memory-mapped register in the controller
 - Two AXI stream interrupt interfaces separately for each cluster
 - Support different interrupt priority for each interrupt source, and they are always software-programmable
- DMAC
 - Micro-code programming based DMA
 - The specific instruction set provides flexibility for programming DMA transfers
 - Linked list DMA function is supported to complete scatter-gather transfer
 - Support internal instruction cache
 - Embedded DMA manager thread

- Support data transfer types with memory-to-memory, memory-to-peripheral, peripheral-to-memory
- Signals the occurrence of various DMA events using the interrupt output signals
- Mapping relationship between each channel and different interrupt outputs is software-programmable
- Two embedded DMA controller, BUS_DMACH is for bus system, PERI_DMACH is for peripheral system
- DMACH0 features:
 - ◆ 6 channels totally
 - ◆ 10 hardware request from peripherals
 - ◆ 2 interrupt output
 - ◆ Dual APB slave interface for register configuration, designated as secure and non-secure
 - ◆ Support Trustzone technology and programmable secure state for each DMA channel
- DMACH1 features:
 - ◆ 8 channels totally
 - ◆ 20 hardware request from peripherals
 - ◆ 2 interrupt output
 - ◆ Dual APB slave interface for register configuration, designated as secure and non-secure
 - ◆ Support Trustzone technology and programmable secure state for each DMA channel
- Security system
 - Support Trustzone technology for the following components inside RK3399
 - ◆ Cortex-A72, support security and non-security mode, switch by software
 - ◆ Cortex-A53, support security and non-security mode, switch by software
 - ◆ Except Cortex-A72 and Cortex-A53, the other masters in the SoC can also support security and non-security mode by software-programmable
 - ◆ Some slave components in SoC can only be addressed by security master and the other slave components can be addressed by security master or non-security master by software-programmable
 - ◆ Internal memory, part of space is addressed only in security mode, detailed size is software-programmable together with TZMA(Trustzone memory adapter)
 - ◆ External DDR space can be divided into eight parts; each part can be software-programmable to be addressed in security mode or non-security mode
 - Embedded dual-channel encryption and decryption engine
 - ◆ Support AES 128/192/256 bits key mode, ECB/CBC/CTR/XTS chain mode, Slave/FIFO mode
 - ◆ Support DES/3DES (ECB and CBC chain mode), 3DES (EDE/EEE key mode), Slave/FIFO mode
 - ◆ Support SHA1/SHA256/MD5(with hardware padding) HASH function, FIFO mode only
 - ◆ Support 160-bit Pseudo Random Number Generator (PRNG)
 - ◆ Support 256-bit True Random Number Generator (TRNG)
 - ◆ Support PKA 512/1024/2048 bit Exp Modulator
 - Support security boot
 - Support security debug

1.2.6 Video CODEC

- Video Decoder
 - MMU embedded
 - Real-time video decoder of MPEG-1, MPEG-2, MPEG-4, H.263, H.264, H.265, VC-1, VP9, VP8, MVC

- H.264/AVC, Base/Main/High/High10 profile @ level 5.1; up to 4Kx2K @ 30fps
- H.265/HEVC, Main/Main10 profile @ level 5.1 High-tier; up to 4Kx2K @ 60fps
- VP9, profile 0, up to 4Kx2K @ 60fps
- MPEG-1, ISO/IEC 11172-2, up to 1080P @ 60fps
- MPEG-2, ISO/IEC 13818-2, SP@ML, MP@HL, up to 1080P @ 60fps
- MPEG-4, ISO/IEC 14496-2, SP@L0-3, ASP@L0-5, up to 1080P @ 60fps
- VC-1, SP@ML, MP@HL, AP@L0-3, up to 1080P @ 60fps
- MVC is supported based on H.264 or H.265, up to 1080P @ 60fps
-
- Supports frame timeout interrupt, frame finish interrupt and bit stream error interrupt
- Error detection and concealment support for all video formats
- Output data format YUV420 semi-planar, YUV400(monochrome), YUV422 is supported by H.264
- For MPEG-4, GMC (global motion compensation) not supported
- For VC-1, up-scaling and range mapping are supported in image post-processor
- For MPEG-4 SP/H.263, using a modified H.264 in-loop filter to implement deblocking filter in post-processor unit
- Video Encoder
 - Support video encoder for H.264 UP to HP@level4.1, MVC and VP8
 - MMU Embedded
 - Only support I and P slices, not B slices
 - Support error resilience based on constrained intra prediction and slices
 - Input data format:
 - ◆ YCbCr 4:2:0 planar
 - ◆ YCbCr 4:2:0 semi-planar
 - ◆ YCbYCr 4:2:2
 - ◆ CbYCrY 4:2:2 interleaved
 - ◆ RGB444 and BGR444
 - ◆ RGB555 and BGR555
 - ◆ RGB565 and BGR565
 - ◆ RGB888 and BRG888
 - ◆ RGB101010 and BRG101010
 - Image size is from 96x96 to 1920x1080(Full HD)
 - Maximum frame rate is up to 1920x1080@30FPS®

1.2.7 JPEG CODEC

- JPEG decoder
 - Input JPEG file: YCbCr 4:0:0, 4:2:0, 4:2:2, 4:4:0, 4:1:1 and 4:4:4 sampling formats
 - Output raw image: YCbCr 4:0:0, 4:2:0, 4:2:2, 4:4:0, 4:1:1 and 4:4:4 semi-planar
 - Decoder size is from 48x48 to 8176x8176(66.8Mpixels)
 - Support JPEG ROI (region of image) decode
 - Maximum data rate® is up to 76million pixels per second
 - Embedded memory management unit(MMU)
- JPEG encoder
 - Input raw image:
 - ◆ YCbCr 4:2:0 planar
 - ◆ YCbCr 4:2:0 semi-planar
 - ◆ YCbYCr 4:2:2
 - ◆ CbYCrY 4:2:2 interleaved
 - ◆ RGB444 and BGR444
 - ◆ RGB555 and BGR555
 - ◆ RGB565 and BGR565
 - ◆ RGB888 and BRG888

- ◆ RGB101010 and BRG101010
- Output JPEG file: JFIF file format 1.02 or Non-progressive JPEG
- Encoder image size up to 8192x8192(64million pixels) from 96x32
- Maximum data rate^④ up to 90million pixels per second
- Embedded memory management unit(MMU)

1.2.8 Image Enhancement

- Image pre-processor
 - Only used together with HD video encoder inside RK3399, not support stand-alone mode
 - Provides RGB to YCbCr 4:2:0 color space conversion, compatible with BT601, BT709 or user defined coefficients
 - Provides YCbCr4:2:2 to YCbCr4:2:0 color space conversion
 - Support cropping operation from 8192x8192 to any supported encoding size
 - Support rotation with 90 or 270 degrees
- Video stabilization
 - Work in combined mode with HD video encoder inside RK3399 and stand-alone mode
 - Adaptive motion compensation filter
 - Support scene detection from video sequence, encodes key frame when scene change noticed
- Image Post-Processor (embedded inside video decoder)
 - Combined with HD video decoder and JPEG decoder, post-processor can read input data directly from decoder output to reduce bus bandwidth
 - Also work as a stand-alone mode, its input data is from image data stored in external memory
 - Input data format:
 - ◆ Any format generated by video decoder in combined mode
 - ◆ YCbCr 4:2:0 semi-planar
 - ◆ YCbCr 4:2:0 planar
 - ◆ YCbYCr 4:2:2
 - ◆ YCrYCb 4:2:2
 - ◆ CbYCrY 4:2:2
 - ◆ CrYCbY 4:2:2
 - Output data format:
 - ◆ YCbCr 4:2:0 semi-planar
 - ◆ YCbYCr 4:2:2
 - ◆ YCrYCb 4:2:2
 - ◆ CbYCrY 4:2:2
 - ◆ CrYCbY 4:2:2
 - ◆ Fully configurable ARGB channel lengths and locations inside 32bits, such as ARGB8888, RGB565, ARGB4444 etc.
 - Input image size:
 - ◆ Combined mode: from 48x48 to 8176x8176 (66.8Mpixels)
 - ◆ Stand-alone mode: width from 48 to 8176, height from 48 to 8176, and maximum size limited to 16.7Mpixels
 - ◆ Step size is 16 pixels
 - Output image size: from 16x16 to 1920x1088 (horizontal step size 8, vertical step size 2)
 - Support image up-scaling:
 - ◆ Bicubic polynomial interpolation with a four-tap horizontal kernel and a two-tap vertical kernel
 - ◆ Arbitrary non-integer scaling ratio separately for both dimensions
 - ◆ Maximum output width is 3x input width
 - ◆ Maximum output height is 3x input height
 - Support image down-scaling:
 - ◆ Arbitrary non-integer scaling ratio separately for both dimensions

- ◆ Unlimited down-scaling ratio
- Support YUV to RGB color conversion, compatible with BT.601-5, BT.709 and user definable conversion coefficient
- Support dithering (2x2 ordered spatial dithering) for 4/5/6bit RGB channel precision
- Support programmable alpha channel and alpha blending operation with the following overlay input formats:
 - ◆ 8bit alpha +YUV444, big endian channel order with AYUV8888
 - ◆ 8bit alpha +24bit RGB, big endian channel order with ARGB8888
- Support de-interlacing with conditional spatial de-interlace filtering, only compatible with YUV420 input format
- Support RGB image contrast/brightness/color saturation adjustment
- Support image cropping & digital zoom only for JPEG or stand-alone mode
- Support picture in picture
- Support image rotation (horizontal flip, vertical flip, rotation 90,180 or 270 degrees)
- Image Enhancement-Processor (IEP)
 - Image format
 - ◆ Input data: XRGB/RGB565/YUV420/YUV422
 - ◆ Output data: ARGB/RGB565/YUV420/YUV422
 - ◆ The format ARGB/XRGB/RGB565/YUV support swap
 - ◆ Support YUV semi-planar/planar
 - ◆ Support BT601_l/BT601_f/BT709_l/BT709_f color space conversion
 - ◆ Support RGB dither up/down conversion
 - ◆ Support YUV up/down sampling conversion
 - ◆ Max resolution for static image up to 8192x8192
 - ◆ Max resolution for dynamic image
 - De-interlace: 1920x1080
 - Sampling noise reduction: 1920x1080
 - Compression noise reduction: 4096x2304
 - Enhancement: 4096x2304
 - Enhancement
 - ◆ Gamma adjustment with programmable mapping table
 - ◆ Hue/Saturation/Brightness/Contrast enhancement
 - ◆ Color enhancement with programmable coefficient
 - ◆ Detail enhancement with filter matrix up to 7x7
 - ◆ Edge enhancement with filter matrix up to 7x7
 - ◆ Programmable difference table for detail enhancement
 - ◆ Programmable distance table for detail and edge enhancement
 - Noise reduction
 - ◆ Compression noise reduction with filter matrix up to 7x7
 - ◆ Programmable difference table for compression noise reduction
 - ◆ Programmable distance table for compression noise reduction
 - ◆ Spatial sampling noise reduction
 - ◆ Temporal sampling noise reduction
 - ◆ Optional coefficient for sampling noise reduction
 - De-interlace
 - ◆ Input 4 fields, output 2 frames mode
 - ◆ Input 4 fields, output 1 frames mode
 - ◆ Input 2 fields, output 1 frames mode
 - ◆ Programmable motion detection coefficient
 - ◆ Programmable high frequency factor
 - ◆ Programmable edge interpolation parameter
 - ◆ Source width up to 1920
 - Embedded memory management unit(MMU)

1.2.9 Graphics Engine

- 3D Graphics Engine:
 - ARM Mali-T860MP4 GPU, support OpenGL ES1.1/2.0/3.0/3.1/3.2, OpenCL1.2, DirectX11.1 etc.
 - Embedded 4 shader cores with shared hierarchical tiler
 - Provide MMU and L2 Cache with 256KB size
 - Image quality using double-precision FP64, and anti-aliasing capabilities
 - 10-bit and 16-bit YUV input and output formats
- 2D Graphics Engine:
 - Source format:
 - ◆ ARGB/RGB888/RGB565/RGB4444/RGB5551/YUV420/YUV422(SupportYUV422SP10bit/YUV420SP10bit)
 - Destination formats:
 - ◆ ARGB/RGB888/RGB565/RGB4444/RGB5551/YUV420/YUV422(Support YVYU422/420 output)
 - Max resolution: 8192x8192 source, 4096x4096 destination
 - Block transfer and Transparency mode
 - Color fill with gradient fill, and pattern fill
 - Alpha blending modes including global alpha, per pixel alpha (color/alpha channel separately) and fading
 - Arbitrary non-integer scaling ratio, from 1/16 to 16
 - 0, 90, 180, 270-degree rotation, x-mirror, y-mirror & rotation operation
 - ROP2, ROP3, ROP4
 - Support 4k/64k page size MMU

1.2.10 Video IN/OUT

- Camera Interface
 - One or two MIPI-CSI input interface
- Image Signal Processor
 - There are two ISP (Image Sensor Processor)built-in
 - Maximum input resolution of one ISP is14M pixels
 - Main scaler with pixel-accurate up-scaling and down-scaling to any resolution between 4416x3312 and 32x16 pixel in processing mode
 - Self scaler with pixel-accurate up-scaling and down-scaling to any resolution between 1920x1080 and 32x16 pixel in processing mode
 - support of semi planar NV21 color storage format
 - support of independent image cropping on main and self-path
 - ITU-R BT 601/656 compliant video interface supporting YCbCr or RGB Bayer data
 - 12-bit camera interface
 - 12-bit resolution per color component internally
 - YCbCr 4:2:2 processing
 - quantization and Huffman tables
 - Windowing and frame synchronization
 - Macro block line, frame end, capture error, data loss interrupts and sync. (h_start, v_start) interrupts
 - Luminance/chrominance and chrominance blue/red swapping for YUV input signals
 - Continuous resize support
 - Color processing (contrast, saturation, brightness, hue, offset, range)
 - Display-ready RGB output in self-picture path (RGB888, RGB666 and RGB565)
 - Rotation unit in self-picture path (90°, 180°, 270° and h/v flipping) for RGB output
 - Read port provided to read back a picture from system memory
 - Simultaneous picture read back, resizing and storing through self path while main path captures the camera picture
 - Black level compensation
 - Four channel Lens shade correction (Vignetting)

- Auto focus measurement
- White balancing and black level measurement
- Auto exposure support by brightness measurement in 5x5 sub windows
- Defect pixel cluster correction unit (DPCC) supports on the fly and table based pixel correction
- De-noising pre filter (DPF)
- Enhanced color interpolation (RGB Bayer demosaicing)
- Chromatic aberration correction
- Combined edge sensitive Sharpening / Blurring filter (Noise filter)
- Color correction matrix (cross talk matrix)
- Global Tone Mapping with wide dynamic range unit (WDR)
- Image Stabilization support and Video Stabilization Measurement
- Flexible Histogram calculation
- Digital image effects (Emboss, Sketch, Sepia, B/W (Grayscale), Color Selection, Negative image, sharpening)
- Solarize effect through gamma correction
- Display Interface
 - Embedded twoVOP, output from the following display interface.
 - ◆ One or Two MIPI-DSI port
 - ◆ One eDP port
 - ◆ One DP port
 - ◆ One HDMI port
 - Support AFBC function co-operation with GPU
 - ◆ decompress FB generated by GPU FBC
 - ◆ support 2560x1600 UI
 - ◆ support ARGB888, RGB888, RGB565
 - ◆ output for one layer among WIN0/1/2/3
 - ◆ only support one IFDBC block which can be used for WIN0/1/2/3 by configuration
- Video Output Processor(VOP_BIG)
 - Display interface
 - ◆ HDMI interface
 - Support 480p/480i/576p/576i/720p/1080p/1080i/4k
 - Support RGB/YUV420(up to 10bit) format
 - ◆ DP interface
 - Support progressive/interlace
 - Support RGB/YUV420/YUV422/YUV444(up to 10bit) format
 - ◆ MIPI interface
 - MIPI DCS command mode
 - Dual-MIPI
 - ◆ EDP interface
 - ◆ Max resolution
 - Max input resolution: 4096x2304
 - Max output resolution: 4096x2160
 - ◆ Scanning timing 8192x4096
 - ◆ Support configurable polarity of DCLK/HSYNC/VSYNC/DEN
 - Display process
 - ◆ CABG
 - ◆ BCSH,10bit
 - ◆ Support display data swap
 - ◆ Support YUV2RGB transition and RGB2YUV transition
 - ◆ Support YUV2YUV
 - ◆ GAMMA
 - ◆ Support blank display and black display
 - ◆ Support standby mode

- ◆ X-MIRROR, Y-MIRROR for win0/win1/win2/win3/hwc
- ◆ scale down for TV over scan
- Layer process
 - ◆ Background layer
 - programmable 30-bit color
 - ◆ Afbcd
 - format: ARGB8888/RGB888/RGB565
 - Support block split
 - win_sel(win0/win1/win2/win3)
 - ◆ Win0/Win1 layer
 - Support data format
 - ✧ RGB888, ARGB888, RGB565,
 - ✧ YCbCr420SP, YCbCr422SP, CbCr444SP, YUYV420, YUYV422, YVYU420, YVYU422
 - ✧ RGB(8bit), YUV(8bit/10bit), YVYU/YUYV(8bit)
 - YUV clip
 - ✧ Y-8bit: 16~235; UV-8bit: 16~240
 - ✧ Y-10bit: 64~940; UV-10bit: 64~960
 - CSC
 - ✧ RGB2YUV, YUV2RGB, RGB2RGB, YUV2YUV
 - Support max input resolution 4096x8192
 - Support max output resolution 4096x2160
 - Support virtual display
 - Support 1/8 to 8 scaling-down and scaling-up engine
 - ✧ scale up using Bicubic and bilinear
 - ✧ scale down using bilinear and average
 - ✧ per-pix alpha + scale
 - Support data swap
 - ✧ RGB/BPP: rb_swap
 - ✧ YUV: mid_swap, uv_swap
 - transparency color key, prior to alpha blending and fading
 - Support fading/alpha blending
 - Support interlace output
 - ◆ Win2/Win3 layer
 - Support data format
 - ✧ RGB888, ARGB888, RGB565
 - ✧ 8BPP
 - ✧ little endian and big endian for BPP
 - ✧ BYPASS and LUT mode(32bit LUT, 8bit AA+8bit-RGB) for BPP
 - CSC
 - ✧ RGB2YUV, RGB2RGB
 - 4 display regions
 - ✧ only one region at one scanning line
 - Support data swap
 - ✧ RGB/BPP:rb_swap
 - Support transparency color key, prior to alpha blending and fading
 - Support fading/alpha blending
 - Support interlace output
 - ◆ Hardware Cursor layer
 - Support data format
 - ✧ RGB888, ARGB888, RGB565
 - ✧ 8BPP
 - ✧ little endian and big endian for BPP
 - ✧ BYPASS and LUT mode(32bit LUT, 8bit AA+8bit-RGB)for BPP
 - CSC
 - ✧ RGB2YUV
 - Support four hwc size: 32x32,64x64,96x96,128x128

- Support 2 color modes: normal and reversed color
 - Support fading/alpha blending
 - Support displaying out of panel, right or bottom
 - Support interlace output
- ◆ Support p2i
- ◆ Overlay
 - support RGB and YUV domain overlay
 - Support 6 layers, background/win0/win1/win2/win3/hwc
 - Win0/Win1/Win2/Win3 overlay position exchangeable
 - Alpha blending
 - ✧ Support multi alpha blending modes
 - ✧ Support pre-multiplied alpha
 - ✧ Support global alpha and per_pix alpha
 - ✧ Support 256 level alpha
 - ✧ Layer0/layer1/layer2/layer3/hwc support alpha
- Write back
 - ◆ Support format
 - RGB565(8bit), RGB888P(8bit)
 - YUV420(8bit)
 - ◆ Support scale
 - horizontal scale down using bilinear, 0.25~1.0
 - vertical throw odd/even line
- Embedded memory management unit(MMU)
- Video Output Processor(VOP_LIT)
 - Display interface
 - ◆ HDMI interface
 - Support 480p/480i/576p/576i/720p/1080p/1080i
 - Support RGB format
 - ◆ DP interface
 - Support progressive/interlace
 - Support RGB/YUV420/YUV422/YUV444format
 - ◆ MIPI interface
 - MIPI DCS command mode
 - Dual-MIPI
 - ◆ EDP interface
 - ◆ Max resolution
 - Max input resolution: 4096x2304
 - Max output resolution: 2560x1600
 - ◆ Scanning timing 8192x4096
 - ◆ Support configurable polarity of DCLK/HSYNC/VSNC/DEN
 - Display process
 - ◆ CABC
 - ◆ BCSH,10bit
 - ◆ Support display data swap
 - ◆ Support YUV2RGB transition and RGB2YUV transition
 - ◆ Support YUV2YUV
 - ◆ GAMMA
 - ◆ Support blank display and black display
 - ◆ Support standby mode
 - ◆ X-MIRROR, Y-MIRROR for win0/win2/hwc
 - ◆ scale down for TV overscan
 - Layer process
 - ◆ Background layer
 - programmable30 bit color
 - ◆ Win0 layer
 - Support data format

- ✧ RGB888, ARGB888, RGB565,
- ✧ YCbCr420SP, YCbCr422SP, CbCr444SP, YUYV420, YUYV422, YVYU420, YVYU422
- ✧ RGB(8bit), YUV(8bit), YVYU/YUYV(8bit)
- YUV clip
 - ✧ Y-8bit: 16~235; UV-8bit: 16~240
- CSC
 - ✧ RGB2YUV, YUV2RGB, RGB2RGB, YUV2YUV
- Support max input resolution 4096x8192
- Support max output resolution 2560x1600
- Support virtual display
- Support 1/8 to 8 scaling-down and scaling-up engine
 - ✧ scale up using Bicubic and bilinear
 - ✧ scale down using bilinear and average
 - ✧ per-pix alpha + scale
- Support data swap
 - ✧ RGB/BPP: rb_swap
 - ✧ YUV: mid_swap,uv_swap
- transparency color key,prior to alpha blending and fading
- Support fading/alpha blending
- Support interlace output
- ◆ Win2 layer
 - Support data format
 - ✧ RGB888, ARGB888, RGB565
 - ✧ 8BPP
 - ✧ little endian and big endian for BPP
 - ✧ BYPASS and LUT mode(32bit LUT, 8bit AA+8bit-RGB) for BPP
 - CSC
 - ✧ RGB2YUV, RGB2RGB
 - 4 display regions
 - ✧ only one region at one scanning line
 - Support data swap
 - ✧ RGB/BPP:rb_swap
 - Support transparency color key, prior to alpha blending and fading
 - Support fading/alpha blending
 - Support interlace output
- ◆ Hardware Cursor layer
 - Support data format
 - ✧ RGB888, ARGB888, RGB565
 - ✧ 8BPP
 - ✧ little endian and big endian for BPP
 - ✧ BYPASS and LUT mode(32bit LUT, 8bit AA+8bit-RGB)for BPP
 - CSC
 - ✧ RGB2YUV
 - Support four hwc size: 32x32,64x64,96x96,128x128
 - Support 2 color modes: normal and reversed color
 - Support fading/alpha blending
 - Support displaying out of panel, right or bottom
 - Support interlace output
- ◆ Support p2i
- ◆ Overlay
 - support RGB and YUV domain overlay
 - Support 4layers, background/win0/win2/hwc
 - Win0/Win2 overlay position exchangeable
 - Alpha blending
 - ✧ Support multi alpha blending modes
 - ✧ Support pre-multiplied alpha

- ✧ Support global alpha and per_pix alpha
- ✧ Support 256 level alpha
- ✧ Layer0/layer2/hwc support alpha
- ◆ Embedded memory management unit(MMU)

1.2.11 HDMI

- Single Physical Layer PHY with support for HDMI 1.4 and 2.0 operation
- For HDMI operation, support for the following:
 - HPD input analog comparator
 - 13.5–600MHz input reference clock
 - Up to 10-bit Deep Color modes
 - Up to 18Gbps aggregate bandwidth
 - Up to 1080p at 120Hz and 4kx2k at 60Hz HDTV display resolutions and up to QXGA graphic display resolutions
 - 3-D video formats
- Link controller flexible interface with 30-, 60- or 120-bit SDR data access
- Support HDCP 1.4/2.2

1.2.12 MIPI PHY

- Embedded 3 MIPI PHY, MIPI0 only for DSI, MIPI1 for DSI or CSI, MIPI2 only for CSI
- Lane operation ranging from 80 Mbps to 1.5 Gbps in forward direction
- Each port has 4 data lane, providing up to 6.0 Gbps data rate
- Support 1080p@60fps output with single channel
- Support 2560x1600@60fps output with MIPI0 and MIPI1 dual channel

1.2.13 eDP PHY

- Compliant with eDP™ Specification, version 1.3
- Support RGB 6/8/10bit video format
- Up to 4 physical lanes of 2.7/1.62 Gbps/lane
- Support VESA DMT and CVT timing standards
- Fully support EIA/CEA-861D video timing and Info Frame structure
- Hot plug and unplug detection and link status monitor
- Supports Panel Self Refresh(PSR)

1.2.14 DisplayPort

- Compliant with DisplayPort Specification, version 1.2
- Compliant with HDCP2.2 (and back compatible with HDCP1.3)
- There is only one DisplayPort controller built-in RK3399 which is shared by 2 Type-C interface
- 25-600Mhz pixel clock
- Supports 8/10 bpp RGB, YCbCr422, YCbCr420 formats
- Supports up to 4kx2k at 60Hz resolution
- Variety of audio formats—PCM and compressed, over I2S or SPDIF interfaces
- 1Mbps AUX channel

1.2.15 TYPE-C Interface

- Embedded 2 Type-C PHY
- Compliant with USB Type-C Specification, revision 1.1
- Compliant with USB Power Delivery Specification, revision 2.0
- Attach/detach detection and signaling as DFP, UFP and DRP
- Plug orientation/cable twist detection
- Enable/disable VBUS as DFP and DRP (when operating as DFP)
- VBUS detection as UFP and DRP (when operating as UFP)
- USB Power Delivery communication across the CC wire
- Support USB3.0 Type-C and DisplayPort 1.2 Alt Mode on USB Type-C. Two PMA TX-only

lanes and two PMA half-duplex TX/RX lanes (can be configured as TX-only or RX-only)

- Up to 5Gbps data rate for USB3.0
- Up to 5.4Gbps(HBR2) data rate for DP1.2, can support 1/2/4 lane mode
- Support DisplayPort AUX channel

1.2.16 Audio Interface

- I2S/PCM
 - Three I2S/PCM in SoC
 - I2S0/I2S2 support up to 8 channels TX and 8 channels RX. I2S1 supports up to 2 channels TX and 2 channels RX
 - I2S2 is connected to HDMI and DisplayPort internally. I2S0 and I2S1 are exposed for peripherals.
 - Audio resolution from 16bits to 32bits
 - Sample rate up to 192KHz
 - Provides master and slave work mode, software configurable
 - Support 3 I2S formats (normal, left-justified, right-justified)
 - Support 4 PCM formats (early, late1, late2, late3)
 - I2S and PCM mode cannot be used at the same time
- SPDIF
 - Support two 16-bit audio data store together in one 32-bit wide location
 - Support biphasic format stereo audio data output
 - Support 16 to 31-bit audio data left or right justified in 32-bit wide sample data buffer
 - Support 16, 20, 24 bits audio data transfer in linear PCM mode
 - Support non-linear PCM transfer

1.2.17 Connectivity

- SDIO interface
 - Compatible with SDIO 3.0 protocol
 - 4bits data bus width
 - There are 2 total MMC interfaces which may be configured as SD/MMC or SDIO
- GMAC 10/100/1000M Ethernet Controller
 - There is one Giga Ethernet interface
 - Supports 10/100/1000-Mbps data transfer rates with the RGMII interfaces
 - Supports 10/100-Mbps data transfer rates with the RMII interfaces
 - Supports both full-duplex and half-duplex operation
 - Preamble and start-of-frame data (SFD) insertion in Transmit, and deletion in Receive paths
 - Automatic CRC and pad generation controllable on a per-frame basis
 - Options for Automatic Pad/CRC Stripping on receive frames
 - Programmable InterFrameGap (40-96 bit times in steps of 8)
 - Supports a variety of flexible address filtering modes
 - Separate 32-bit status returned for transmission and reception packets
 - Supports IEEE 802.1Q VLAN tag detection for reception frames
 - Support detection of LAN wake-up frames and AMD Magic Packet frames
 - Support checksum off-load for received IPv4 and TCP packets encapsulated by the Ethernet frame
 - Support checking IPv4 header checksum and TCP, UDP, or ICMP checksum encapsulated in IPv4 or IPv6 datagrams
 - Comprehensive status reporting for normal operation and transfers with errors
 - Automatic generation of PAUSE frame control or backpressure signal to the GMAC core based on Receive FIFO-fill (threshold configurable) level
 - Handles automatic retransmission of Collision frames for transmission
 - Discards frames on late collision, excessive collisions, excessive deferral and

underrun conditions

- SPI Controller
 - 6 on-chip SPI controllers are inside
 - Support serial-master and serial-slave mode, software-configurable
 - DMA-based or interrupt-based operation
 - Embedded two 32x16bits FIFO for TX and RX operation respectively
- UART Controller
 - 5 on-chip UART controllers inside RK3399
 - DMA-based or interrupt-based operation
 - Embedded two 64Bytes FIFO for TX and RX operation respectively
 - Support 5bit, 6bit, 7bit, 8bit serial data transmit or receive
 - Standard asynchronous communication bits such as start, stop and parity
 - Support different input clock for UART operation to get up to 4Mbps or other special baud rate
 - Support non-integer clock divides for baud clock generation
 - Support auto flow control mode for UART0 and UART3
- I2C controller
 - 9 on-chip I2C controllers
 - Multi-master I2C operation
 - Support 7bits and 10bits address mode
 - Serial 8bits oriented and bidirectional data transfers can be made
 - Software programmable clock frequency
 - Data on the I2C-bus can be transferred at rates of up to 100 kbit/s in the Standard-mode, up to 400 kbit/s in the Fast-mode or up to 1 Mbit/s in Fast-mode Plus.
- GPIO
 - 5 groups of GPIO (GPIO0~GPIO4), totally have 122 GPIOs
 - All of GPIOs can be used to generate interrupt to CPU
 - GPIO0 and GPIO1 can be used to wakeup system from low-power mode
 - The pull direction (pull-up or pull-down) for all of GPIOs are software-programmable
 - All of GPIOs are always in input direction in default after power-on-reset
 - The drive strength for all of GPIOs is software-programmable
- USB OTG3.0
 - Embedded 2 USB OTG3.0 interfaces
 - Compatible Specification
 - ◆ Universal Serial Bus 3.0 Specification, Revision 1.0
 - ◆ Universal Serial Bus Specification, Revision 2.0
 - ◆ eXtensible Host Controller Interface for Universal Serial Bus (xHCI), Revision 1.1
 - Support Control/Bulk (including stream)/Interrupt/Isochronous Transfer
 - Simultaneous IN and OUT transfer for USB3.0, up to 8Gbps bandwidth
 - Descriptor Caching and Data Pre-fetching
 - USB3.0 Device Features
 - ◆ Up to 7 IN endpoints, including control endpoint 0
 - ◆ Up to 6 OUT endpoints, including control endpoint 0
 - ◆ Up to 13 endpoint transfer resources, each one for each endpoint
 - ◆ Flexible endpoint configuration for multiple applications/USB set-configuration modes
 - ◆ Hardware handles ERDY and burst
 - ◆ Stream-based bulk endpoints with controller automatically initiating data movement
 - ◆ Isochronous endpoints with isochronous data in data buffers

- ◆ Flexible Descriptor with rich set of features to support buffer interrupt moderation, multiple transfers, isochronous, control, and scattered buffering support
- USB 3.0 xHCI Host Features
 - ◆ Support up to 64 devices
 - ◆ Support 1 interrupter
 - ◆ Support 1 USB2.0 port and 1 Super-Speed port
 - ◆ Concurrent USB3.0/USB2.0 traffic, up to 8.48Gbps bandwidth
 - ◆ Support standard or open-source xHCI and class driver
 - ◆ Support xHCI Debug Capability
- USB 3.0 Dual-Role Device (DRD) Features
 - ◆ Static Device operation
 - ◆ Static Host operation
 - ◆ USB3.0/USB2.0 OTG A device and B device basing on ID
 - ◆ UFP/DFP and Data Role Swap Defined in USB TypeC Specification
 - ◆ Not support USB3.0/USB2.0 OTG session request protocol(SRP), host negotiation protocol(HNP) and Role Swap Protocol(RSP)
- USB 2.0 Host
 - Embedded 2 USB 2.0 Host interfaces
 - Compatible with USB 2.0Host specification
 - Supports high-speed(480Mbps), full-speed(12Mbps) and low-speed(1.5Mbps) mode
 - Provides 16 host mode channels
 - Support periodic out channel in host mode
- PCIe
 - One PCIe port in RK3399
 - Compatible with PCI Express Base Specification Revision 2.1
 - Dual operation mode: Root Complex(RC)
 - Maximum link width is 4, single bi-directional Link interface
 - Support 2.5GT/s serial data transmission rate per lane per direction
 - Support DMA within the module, 2 channels, 2 RAM partitions, 2K bytes depth
 - Support Resizable BAR Capability
 - Support Single Physical PCI Functions in Endpoint Mode
 - Support Legacy Interrupt and MSI and MSI-X interrupt
 - Support Outbound and Inbound Address Translation
 - Support 8 Virtual Functions attached to Physical Function
 - Support PCI Express Active State Power Management (ASPM) state L0s and L1
 - Support L1 Power Management Substate
 - Support PCI Function power states D0, D1 and D3, and the corresponding link power states L0, L1 and L2

1.2.18 Others

- Temperature Sensor(TS-ADC)
 - Embedded 2 channel TS-ADC in RK3399
 - TS-ADC clock must be less than 800KHZ
 - 10-bits TS-ADC up to 50KS/s sampling rate
 - -40~125C temperature range and 5°C temperature resolution
- SAR-ADC (Successive Approximation Register)
 - 6-channel single-ended 10-bit SAR analog-to-digital converter
 - SAR-ADC clock must be less than 13MHZ
 - Conversion speed range is up to 1MS/s sampling rate
- eFuse
 - Two 1024bits(32x32) high-density electrical Fuse are integrated in RK3399
 - Support standby mode and power down mode

- Embedded power-switch
- Embedded four redundancy bits
- Package Type
 - FCBGA828(body: 21mmx21mm; ball size: 0.35mm; ball pitch: 0.65mm)

Notes :^① : *DDR3/DDR3L/LPDDR3/LPDDR4 could not be used simultaneously*

^② : *Actual maximum frame rate will depend on the clock frequency and system bus performance*

^③ : *Actual maximum data rate will depend on the clock frequency and JPEG compression rate*

1.3 Block Diagram

The following diagram shows the basic block diagram.

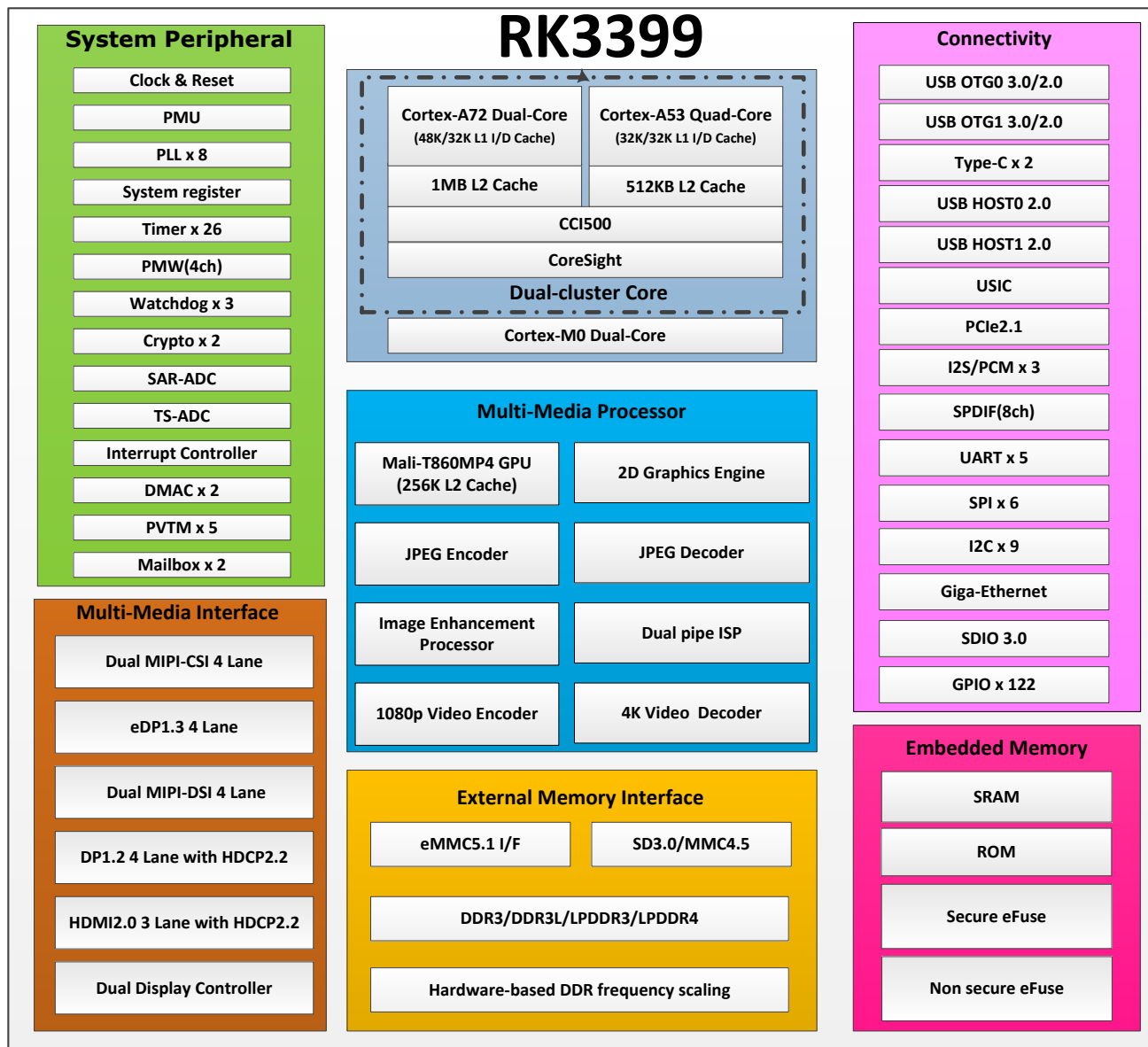


Fig. 1-1 Block Diagram

Chapter 2 Package information

2.1 Ordering information

Orderable Device	RoHS status	Package	Package Qty	Device Feature
RK3399	RoHS	FCBGA828	600 by tray	1.8GA72AP
RK3399K	RoHS	FCBGA828	600 by tray	2.0GA72AP for commercial application

2.2 Top Marking

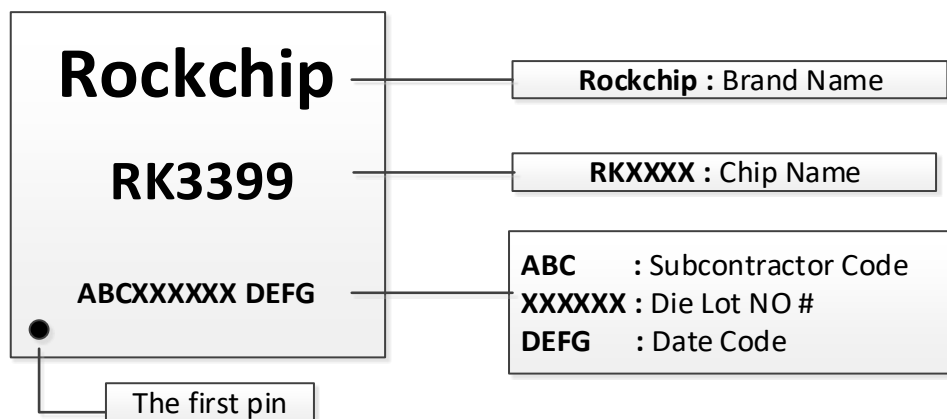


Fig. 2-1RK3399 Top Marking

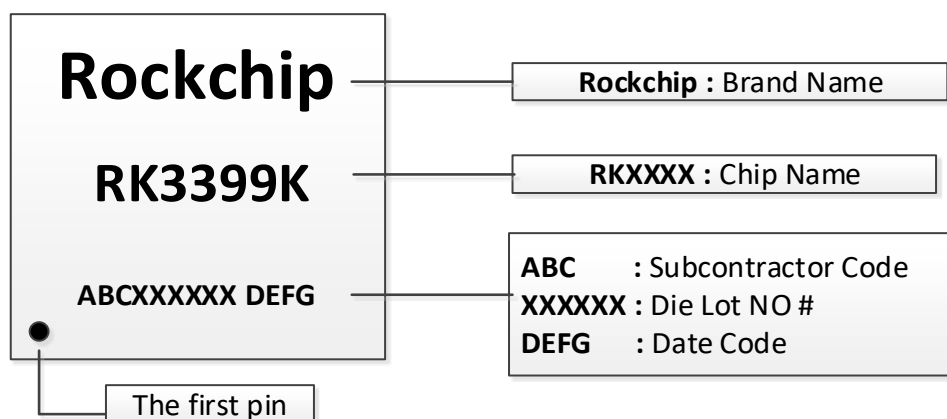


Fig. 2-2RK3399K Top Marking

2.3 Dimension

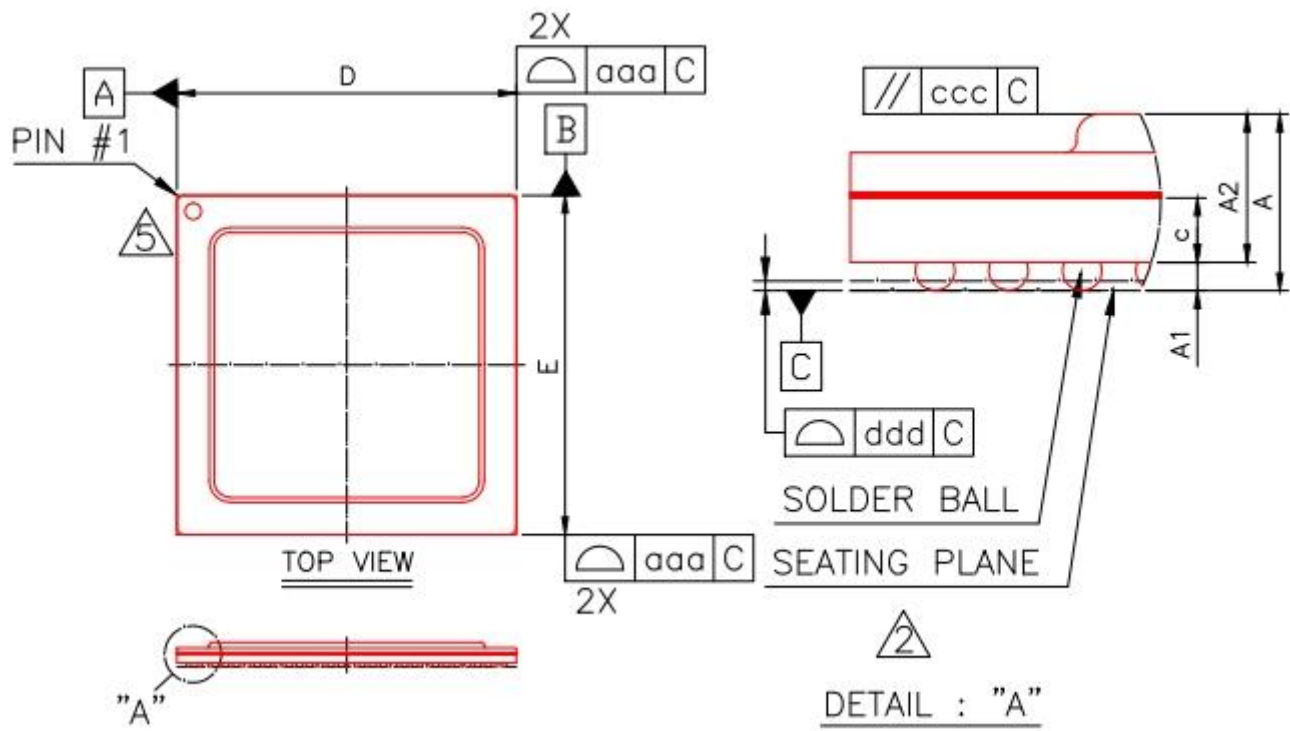


Fig. 2-3 Package Top and Side View

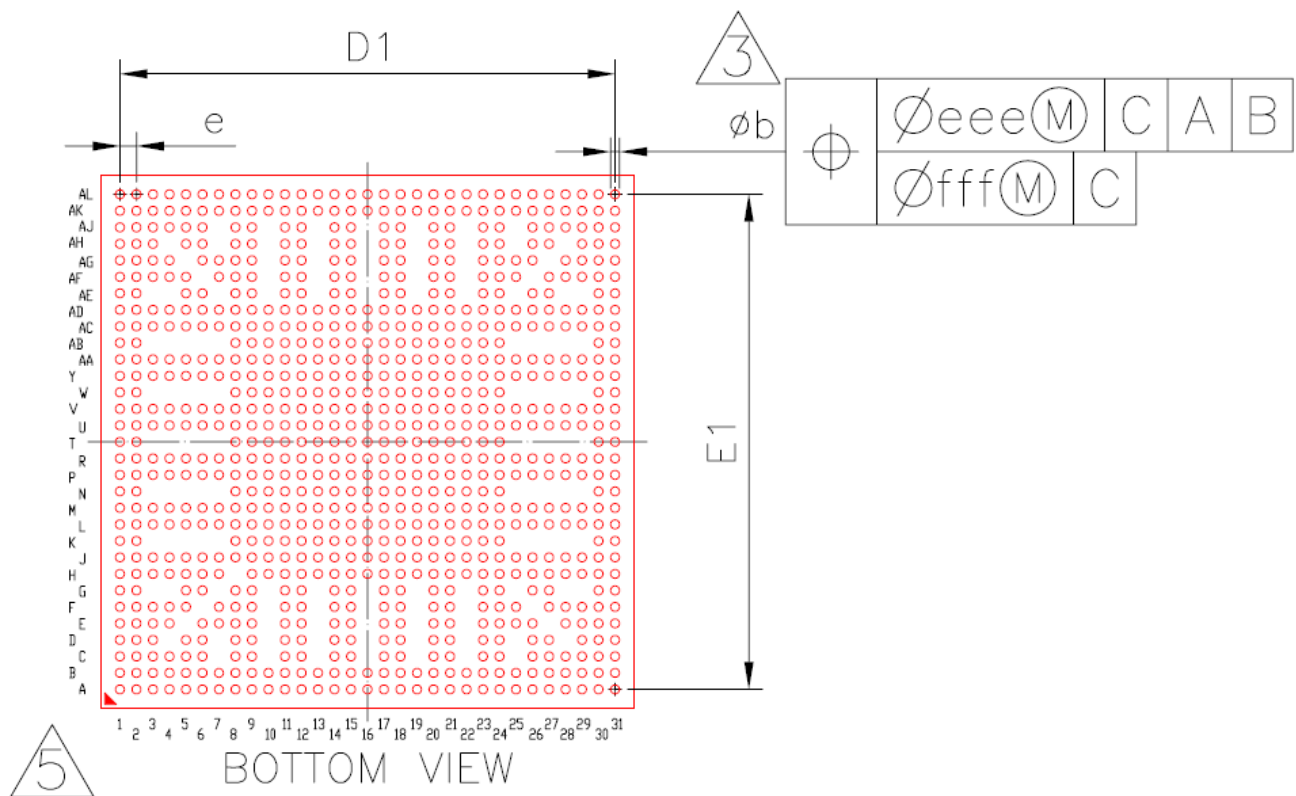


Fig. 2-4 Package Bottom View

Symbol	Dimension in mm			Dimension in inch		
	MIN	NORMAL	MAX	MIN	NORMAL	MAX
A	1.41	1.51	1.61	0.056	0.059	0.063
A1	0.20	0.25	0.30	0.008	0.010	0.012
A2	1.11	1.26	1.41	0.044	0.050	0.056

Symbol	Dimension in mm			Dimension in inch		
C	0.47	0.57	0.67	0.019	0.022	0.026
D	20.90	21.00	21.15	0.823	0.827	0.833
E	20.90	21.00	21.15	0.823	0.827	0.833
D1	---	19.50	---	---	0.768	---
E1	---	19.50	---	---	0.768	---
e	---	0.65	---	---	0.026	---
b	0.30	0.35	0.40	0.012	0.014	0.016
aaa	0.20			0.008		
ccc	0.25			0.010		
ddd	0.20			0.008		
eee	0.25			0.010		
fff	0.10			0.004		

Fig.2-5Package Dimension

Notes :

- 1) Controlling dimension: millimeter
- 2) Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
- 3) Dimension b is measured at the maximum solder ball diameter, parallel to primary datum C.
- 4) Special characteristics C class: A, ddd
- 5) The pattern of pin 1 fiducial is for reference only.
- 6) The tilt of heat sink should be within 10mil(0.254mm) (vertical position)

2.4 Ball Map

Fig. 2-6 Ball Mapping Diagram

	1	2	3	4	5	6	7	8
A	VSS_1	DDR1_CSN1	DDR1_A12	DDR1_A10	DDR1_CKE0	DDR1_A9	DDR1_A7	DDR1_A5
B	DDR0_CSN1	DDR1_BA0	DDR1_CSN3	DDR1_A13	VSS_24	DDR1_A8	DDR1_A6	DDR1_A4
C	DDR0_A12	DDR0_CSN3	DDR0_BA0	DDR1_A14	DDR1_A11	DDR1_RASN	NP	VSS_25
D	DDR0_A10	DDR0_A13	DDR0_A14	NP	VSS_38	DDR1_BA1	NP	DDR1_CLK0N
E	DDR0_CKE0	VSS_39	DDR0_A11	VSS_40	NP	DDR1_CKE1	VSS_41	DDR1_CLK1N
F	DDR0_A1	DDR0_A0	DDR0_RASN	DDR0_BA1	DDR0_CKE1	NP	DDR1_WEN	VSS_48
G	DDR0_A2	DDR0_A3	NP	NP	VSS_53	DDR0_WEN	NP	DDR1_A15
H	DDR0_A5	DDR0_A4	VSS_57	DDR0_CLK0 P	DDR0_CLK1 P	DDR0_CAS N	DDR0_A15	NP
J	DDR0_A6	DDR0_A7	VSS_68	DDR0_CLK0 N	DDR0_CLK1 N	VSS_69	VSS_70	VSS_71
K	DDR0_A9	DDR0_A8	NP	NP	NP	NP	NP	VSS_74
L	DDR0_DQ 29	DDR0_DQ3 1	VSS_85	DDR0_ODT0	DDR0_ODT 1	VSS_86	DDR0_RESETN	VSS_87
M	DDR0_DQ 27	DDR0_DQ3 0	VSS_10 0	DDR0_BA2	DDR0_CSN 2	DDR0_CSN 0	DDR0_CLK_VD D	VSS_101
N	DDR0_DQ 26	DDR0_DQ2 8	NP	NP	NP	NP	NP	VSS_105
P	DDR0_DQ 24	DDR0_DQ2 5	VSS_11 2	DDR0_DQS3 P	DDR0_DM3	VSS_113	VSS_114	VSS_115
R	DDR0_DQ 23	DDR0_DQ2 2	VSS_12 3	DDR0_DQS3 N	VSS_124	VSS_125	DDR0_PZQ	DDR0PLL_AVDD_ 0V9

	1	2	3	4	5	6	7	8
T	DDR0_D Q20	DDR0_D Q21	NP	NP	NP	NP	NP	VSS_134
U	DDR0_D Q18	DDR0_D Q19	VSS_1 41	DDR0_DQ S2P	DDR0_D M2	DDR0_ATB0	DDR0_ATB1	VSS_142
V	DDR0_D Q16	DDR0_D Q17	VSS_1 51	DDR0_DQ S2N	VSS_15 2	DDR0_PLL_TESTOUT _P	DDR0_PLL_TESTOU T_N	VSS_153
W	DDR0_D Q6	DDR0_D Q7	NP	NP	NP	NP	NP	VSS_161
Y	DDR0_D Q5	DDR0_D Q4	VSS_8	DDR0_DQ S0P	DDR0_D M0	GPIO4_A2/I2C1_SCL	GPIO3_D3/I2S0_SD IO	APIO5_VDD
AA	DDR0_D Q3	DDR0_D Q2	VSS_4	DDR0_DQ S0N	VSS_5	GPIO3_D5/I2S0_SDI 2SDO2	GPIO4_A4/I2S1_LR CK_RX	APIO5_VDDP ST
AB	DDR0_D Q1	DDR0_D Q0	NP	NP	NP	NP	NP	APIO3_VDD_ 1V8
AC	DDR0_D Q14	DDR0_D Q15	VSS_1 6	DDR0_DQ S1P	DDR0_D M1	GPIO4_A7/I2S1_SDO 0	GPIO4_A0/I2S_CLK	APIO4_VDDP ST

A	DDR0_D Q13	DDR0_DQ1 1	VSS_17	DDR0_DQS1N	VSS_18	GPIO4_A6/I 2S1_SDI0	GPIO4_C7/HDM I_CECINOUT/E DP_HOTPLUG	GPIO2_C4/ SDIO0_D0/ SPI5_RXD
A	DDR0_D Q12	DDR0_DQ9	NP	NP	GPIO3_D4/I2S 0_SDI1SDO3	GPIO4_D0/P CIE_CLKRE QNB	NP	GPIO2_C7/ SDIO0_D3/ SPI5_CSN0
A	DDR0_D Q10	DDR0_DQ8	GPIO4_ A3/I2S1 _SCLK	GPIO3_D1/I2S 0_LRCK_RX	GPIO4_C2/PW M0/VOP0_PWM /VOP1_PWM	NP	GPIO2_D1/SDI O0_CLKOUT/TE ST_CLKOUT1	GPIO2_D4/ SDIO0_BKP WR
A	GPIO4_A 1/I2C1_S DA	VSS_21	GPIO3_ D0/I2S 0_SCLK	GPIO4_D6	NP	GPIO4_C0/I 2C3_SDA/U ART2B_RX	GPIO2_C6/SDI O0_D2/SPI5_CL K	GPIO2_C2/ UART0_CTS N
A	GPIO3_D 7/I2S0_S DO0	GPIO3_D6/I 2S0_SDI3S DO1	GPIO4_ D2	NP	GPIO4_D4	GPIO2_D0/ SDIO0_CMD	NP	GPIO2_C1/ UART0_TX
A	GPIO4_A 5/I2S1_L RCK_TX	GPIO3_D2/I 2S0_LRCK_ TX	GPIO4_ D5	GPIO4_C4/UA RT2C_TX	VSS_22	AVSS_31	NP	AVSS_32
A	GPIO4_C 5/SPDIF_ TX	GPIO4_C3/ UART2C_RX	GPIO4_ D3	GPIO4_D1/DP _HOTPLUG	GPIO2_C5/SDI O0_D1/SPI5_T XD	MIPI_TX1/R X1_D0P	MIPI_TX1/RX1_ D1P	MIPI_TX1/R X1_CLKP
A	VSS_23	GPIO4_C1/I 2C3_SCL/U ART2B_TX	GPIO4_ C6/PW M1	GPIO2_D2/SD IO0_DETNI/PCI E_CLKREQN	GPIO2_C3/UAR T0_RTSN	MIPI_TX1/R X1_D0N	MIPI_TX1/RX1_ D1N	MIPI_TX1/R X1_CLKN
	1	2	3	4	5	6	7	8

	9	10	11	12	13	14	15	16
A	DDR1_A3	DDR1_A1	DDR1_DQ10	DDR1_DQ12	DDR1_DQ13	DDR1_DQ14	DDR1_DQ1	DDR1_DQ3
B	DDR1_A2	DDR1_A0	DDR1_DQ8	DDR1_DQ9	DDR1_DQ11	DDR1_DQ15	DDR1_DQ0	DDR1_DQ2
C	VSS_26	NP	VSS_27	VSS_28	NP	VSS_29	VSS_30	NP
D	DDR1_CLK0P	NP	DDR1_ODT0	DDR1_BA2	NP	DDR1_DQS1N	DDR1_DQS1P	NP
E	DDR1_CLK1P	NP	DDR1_ODT1	VSS_42	NP	DDR1_DM1	VSS_43	NP
F	DDR1_CASN	NP	DDR1_CSN2	DDR1_CSN0	NP	DDR1_PLL_TESTOUT_P	VSS_49	NP
G	VSS_54	NP	DDR1_RESETN	DDR1_CLK_VDD	NP	DDR1_PLL_TESTOUT_N	DDR1_PZQ	NP

	9	10	11	12	13	14	15	16
H	VSS_58	VSS_59	VSS_60	VSS_61	VSS_62	DDR1PLL_AVDD0V9	VSS_63	VSS_64
J	VSS_72	VSS_73	DDR1_VDD_1	DDR1_VDD_2	DDR1_VDD_3	DDR1_VDD_4	DDR1_VDD_5	DDR1_VDD_6
K	VSS_75	VSS_76	DDR1_VDD_9	VSS_77	DDR1_VDD_10	VSS_78	DDR1_VDD_11	VSS_79
L	DDR0_VDD_1	DDR0_VDD_2	VSS_88	VSS_89	VSS_90	VSS_91	VSS_92	VSS_93
M	DDR0_VDD_3	VSS_102	CENTERLOGIC_VDD_1	CENTERLOGIC_VDD_2	CENTERLOGIC_VDD_3	CENTERLOGIC_VDD_4	CENTERLOGIC_VDD_5	VSS_103
N	DDR0_VDD_4	DDR0_VDD_5	CENTERLOGIC_VDD_6	CENTERLOGIC_VDD_7	VSS_108	VSS_109	VSS_110	VSS_111
P	DDR0_VDD_6	VSS_116	VSS_106	VSS_107	CENTERLOGIC_VDD_8	CENTERLOGIC_VDD_9	CENTERLOGIC_VDD_10	VSS_117
R	DDR0_VDD_7	DDR0_VDD_8	GPU_VDD_8	GPU_VDD_9	GPU_VDD_13	VSS_129	VSS_130	VSS_131

	9	10	11	12	13	14	15	16
T	DDR0_VD D_9	VSS_135	GPU_VD D_10	GPU_VDD_11	GPU_VD D_12	GPU_VDD_14	GPU_VDD _COM	VSS_138
U	DDR0_VD D_10	DDR0_VDD_11	VSS_126	VSS_127	GPU_VD D_7	VSS_137	VSS_143	VSS_144
V	DDR0_VD D_12	VSS_154	GPU_VD D_15	GPU_VDD_16	GPU_VD D_6	GPU_VDD_5	GPU_VDD _4	GPU_VDD_17
W	VSS_162	GPU_VDD_20	GPU_VD D_1	GPU_VDD_2	VSS_128	GPU_VDD_3	GPU_VDD _19	GPU_VDD_18
Y	VSS_166	VSS_15	VSS_155	VSS_136	VSS_164	VSS_156	VSS_157	VSS_118
A A	VSS_6	VSS_179	AVSS_13	AVSS_17	VSS_177	AVSS_26	AVSS_53	HDMI_AVDD _0V9_1
A B	VSS_9	AVSS_12	AVSS_8	MIPI_TX0_AV DD_1V8	AVSS_9	MIPI_RX0_AV DD_1V8	AVSS_42	AVSS_41
A C	APIO4_V DD	MIPI_TX1/RX1_A VDD_1V8	AVSS_44	NC_7	AVSS_45	NC_4	AVSS_10	AVSS_18

A D	GPIO2_D3/SDIO0 _PWREN	VSS_19	NC_2	NC_3	AVSS_11	NC_5	NC_6	HDMI_AVDD D_1V8
A E	GPIO2_C0/UART0 _RX	NP	AVSS_21	AVSS_22	NP	AVSS_23	HDMI_HP D	NP
A F	VSS_20	NP	MIPI_TX1/RX 1_REXT	MIPI_TX0_ REXT	NP	MIPI_RX0_ _REXT	HDMI_RE XT	NP
A G	MIPI_TX0_D3P	NP	MIPI_TX0_D2 P	MIPI_TX0_ CLKP	NP	MIPI_TX0_ D1P	MIPI_TX0 _D0P	NP
A H	MIPI_TX0_D3N	NP	MIPI_TX0_D2 N	MIPI_TX0_ CLKN	NP	MIPI_TX0_ D1N	MIPI_TX0 _D0N	NP
A J	AVSS_33	NP	AVSS_34	AVSS_35	NP	AVSS_36	AVSS_37	NP
A K	MIPI_TX1/RX1_D 2P	MIPI_TX1/RX 1_D3P	MIPI_RX0_D3 P	MIPI_RX0_ _D2P	MIPI_RX0_ CLKP	MIPI_RX0_ _D1P	MIPI_RX0 _D0P	HDMI_TCP
A L	MIPI_TX1/RX1_D 2N	MIPI_TX1/RX 1_D3N	MIPI_RX0_D3 N	MIPI_RX0_ _D2N	MIPI_RX0_ CLKN	MIPI_RX0_ _D1N	MIPI_RX0 _D0N	HDMI_TCN
	9	10	11	12	13	14	15	16

	0	17	18	19	20	21	22	23	24
A		DDR1_D Q5	DDR1_D Q6	DDR1_D Q16	DDR1_D Q18	DDR1_D Q20	DDR1_D Q23	DDR1_DQ24	DDR1_DQ26
B		DDR1_D Q4	DDR1_D Q7	DDR1_D Q17	DDR1_D Q19	DDR1_D Q21	DDR1_D Q22	DDR1_DQ25	DDR1_DQ28
C		VSS_31	VSS_32	NP	VSS_33	VSS_34	NP	VSS_35	VSS_36
D		DDR1_D QS0N	DDR1_D QS0P	NP	DDR1_D QS2N	DDR1_D QS2P	NP	DDR1_DQS3N	DDR1_DQS3P
E		DDR1_D M0	VSS_44	NP	DDR1_D M2	VSS_45	NP	DDR1_DM3	VSS_46
F		DDR1_AT B0	VSS_50	NP	VSS_51	VSS_52	NP	GPIO3_B2/MAC_RXER /I2C5_SDA	GPIO3_A0/MAC_TXD2 /SPI4_RXD
G		DDR1_AT B1	VSS_55	NP	EDP_DC_ TP	EDP_REX T	NP	GPIO3_A5/MAC_TXD1 /SPI0_TXD	GPIO3_B3/MAC_CLK/I 2C5_SCL

	828	17	18	19	20	21	22	23	24
H		VSS_65	VSS_66	EDP_AVSS S_5	EDP_AVDD _0V9	EDP_CLK2 4M_IN	GPIO3_B4/MAC _TXEN/UART1_ RX	GPIO3_A1/MAC _TXD3/SPI4_T XD	GPIO2_B2/SPI2_T XD/CIF_CLKIN/I2 C6_SCL
J		DDR1_VD D_7	DDR1_VD D_8	EDP_AVDD D_1V8_1	EDP_AVDD _1V8_2	EDP_AVSS S_6	APIO1_VDDPST	APIO1_VDD	APIO2_VDDPST
K		DDR1_VD D_12	VSS_80	BIGCPU_ VDD_12	VSS_82	BIGCPU_ VDD_13	VSS_84	APIO2_VDD	EMMC_VDD_1V8
L		LOGIC_V DD_10	BIGCPU_ VDD_8	BIGCPU_ VDD_1	VSS_96	BIGCPU_ VDD_2	VSS_97	BIGCPU_VDD_ 11	EMMC_COREDLL_ 0V9
M		LOGIC_V DD_9	BIGCPU_ VDD_3	BIGCPU_ VDD_4	BIGCPU_VD D_5	BIGCPU_ VDD_6	BIGCPU_VDD_ 7	VSS_104	GPIO1_B5
N		VSS_94	BIGCPU_ VDD_CO M	VSS_83	BIGCPU_VD D_10	VSS_98	BIGCPU_VDD_ 9	PMUIO2_VDDP ST	GPIO0_A2/WIFI_2 6MHZ
P		PLL_AVSS	PLL_AVDD D_1V8	VSS_119	LITCPU_VD D_1	VSS_121	LITCPU_VDD_4	PMUIO2_VDD	GPIO0_B5/TCPD_ VBUS_FDIS/TCPD _VBUS_SOURCE3
R		PLL_AVDD _0V9	VSS_165	LITCPU_V DD_2	LITCPU_VD D_3	VSS_120	LITCPU_VDD_7	VSS_133	PMUIO1_VDD_1V 8

	0	17	18	19	20	21	22	23	24
T		LOGIC_VDD_11	VSS_168	VSS_122	LITCPU_VDD_6	VSS_139	LITCPU_VDD_5	SDMMC0_VDD	PMU_VDD_0V9
U		LOGIC_VDD_8	LOGIC_VDD_7	VSS_146	LOGIC_VDD_12	VSS_147	VSS_149	AVSS_49	USB_AVD_1V8
V		VSS_148	LOGIC_VDD_5	LOGIC_VDD_4	LOGIC_VDD_3	LOGIC_VDD_2	LOGIC_VDD_1	AVSS_50	USB_AVD_0V9
W		VSS_159	VSS_169	VSS_167	LOGIC_VDD_6	VSS_81	VSS_158	AVSS_46	PCIE_AVD_0V9
Y		VSS_95	TYPEC0_AVDD_0V9_2	TYPEC0_AVDD_0V9_1	VSS_170	TYPEC1_AVDD_0V9_1	TYPEC1_AVDD_0V9_2	AVSS_1	PCIE_AVD_1V8
A		HDMI_AVDD_0V9_2	TYPEC0_AVDD_1V8	NC_8	NC_9	TYPEC1_AVDD_1V8	NC_11	AVSS_4	DFTJTAG_TMS
A		AVSS_52	TYPEC0_AVDD_3V3	VSS_140	NC_10	TYPEC1_AVDD_3V3	NC_1	AVSS_5	DFTJTAG_TRSTN
A		AVSS_43	VSS_145	TYPEC1_U3VB_USDET	VSS_13	VSS_132	VSS_12	AVSS_19	ADC_AVD
C									D

A	AVSS_16	TYPEC0_RCLKM	TYPEC0_U3VB_USDET	TYPEC1_RCLKM	VSS_163	VSS_11	EFUSE	USIC_AVDD_1V2
A	AVSS_24	TYPEC0_RCLKP	NP	TYPEC1_RCLKP	TYPEC1_REXT	NP	VSS_14	TYPEC1_AUXP_PD_PU
A	AVSS_27	VSS_7	NP	VSS_10	TYPEC1_CC2	NP	AVSS_2	AVSS_3
A	TYPEC0_AUXM_PD_PU	TYPEC0_REXT	NP	TYPEC0_REXT_CC	TYPEC1_REXT_CC	NP	TYPEC0_DP	TYPEC1_DP
A	TYPEC0_AUXP_PD_PU	TYPEC0_CC1	NP	TYPEC0_CC2	TYPEC1_CC1	NP	TYPEC0_DN	TYPEC1_DN
A	AVSS_38	AVSS_39	NP	VSS_180	VSS_172	NP	VSS_173	VSS_174
A	HDMI_TX0P	HDMI_TX1P	HDMI_TX2P	TYPEC0_AUXP	TYPEC0_RX1P	TYPEC0_TX1M	TYPEC0_RX2P	TYPEC0_TX2M
A	HDMI_TX0N	HDMI_TX1N	HDMI_TX2N	TYPEC0_AUXM	TYPEC0_RX1M	TYPEC0_TX1P	TYPEC0_RX2M	TYPEC0_TX2P
L								
	17	18	19	20	21	22	23	24

25	26	27	28	29	30	31	0
DDR1_DQ27	DDR1_DQ29	VSS_2	EDP_AUXN	EDP_TX0N	EDP_TX1N	VSS_3	A
DDR1_DQ30	DDR1_DQ31	GPIO3_B7/MAC_C RS/UART3_TX/CIF _CLKOUTB	EDP_AUXP	EDP_TX0P	EDP_TX1P	EDP_AVSS_1	B
NP	VSS_37	GPIO3_B1/MAC_R XDV	EDP_AVSS_2	EDP_AVSS_3	EDP_TX2P	EDP_TX2N	C
NP	GPIO3_A4/M AC_TXD0/SP IO_RXD	GPIO3_C0/MAC_C OL/UART3_CTSN/ SPDIF_TX	NP	EDP_AVSS_4	EDP_TX3P	EDP_TX3N	D
GPIO3_A3/M AC_RXD3/SP I4_CSN0	GPIO3_A6/M AC_RXD0/SP IO_CLK	NP	GPIO3_C1/MA C_TXCLK/UAR T3_RTSN	GPIO3_B0/M AC_MDC/SPI 0_CSN1	GPIO3_A2/MAC_ RXD2/SPI4_CLK	VSS_47	E
GPIO3_B6/M AC_RXCLK/U ART3_RX	NP	GPIO3_A7/MAC_R XD1/SPI0_CSN0	GPIO2_A3/VO P_D3/CIF_D3	GPIO2_A5/V OP_D5/CIF_ D5	GPIO2_B1/SPI2 _RXD/CIF_HREF /I2C6_SDA	GPIO2_B4/SPI 2_CSN0	F
NP	GPIO3_B5/M AC_MDIO/U ART1_TX	VSS_56	NP	NP	GPIO2_A7/VOP_ D7/CIF_D7/I2C7 _SDA	GPIO2_A0/VO P_D0/CIF_D0/ I2C2_SDA	G

25	26	27	28	29	30	31	0
GPIO2_A1/VOP_D1 /CIF_D1/I2C2_SCL	VSS_67	GPIO2_A6/VO P_D6/CIF_D6	GPIO2_B0/VOP _CLK/CIF_VSY NC/I2C7_SCL	GPIO2_A4/V OP_D4/CIF_ D4	GPIO2_A 2/VOP_D 2/CIF_D2	GPIO2_B3/S PI2_CLK/VOP _DEN/CIF_C LKOUTA	H
EMMC_D3	EMMC_D4	EMMC_D5	EMMC_D0	EMMC_D1	EMMC_D 2	EMMC_CMD	J
NP	NP	NP	NP	NP	EMMC_D 7	EMMC_STRB	K
GPIO1_C6/TCPD_V BUS_SOURCE0	GPIO1_D0/TCPD_V BUS_SOURCE2	VSS_99	EMMC_CLK	EMMC_CALI O	EMMC_TP	EMMC_D6	L
GPIO1_B6/PWM3B _IR	GPIO1_B7/SPI3_RX D/I2C0_SDA	GPIO1_C1/SPI 3_CLK	GPIO1_C3/PW M2	GPIO1_C4/I 2C8_SDA	GPIO1_C 5/I2C8_S CL	GPIO1_C7/T CPD_VBUS_ SOURCE1	M
NP	NP	NP	NP	NP	GPIO1_C 0/SPI3_T XD/I2C0 _SCL	GPIO1_C2/S PI3_CSN0	N
GPIO0_A6/PWM3A _IR	GPIO1_A6/TSADC_ INT	GPIO1_A7/SPI 1_RXD/UART4 _RX	GPIO1_B1/SPI 1_CLK/PMCU_J TAG_TCK	GPIO1_B2/S PI1_CSN0/P MCU_JTAG_ TMS	GPIO1_B 4/I2C4_S CL	GPIO1_B3/I2 C4_SDA	P
GPIO1_A0/ISP0_S HUTTER_EN/ISP1_ SHUTTER_EN/TCPD _VBUS_SINK_EN	GPIO1_A2/ISP0_FL ASHTRIGIN/ISP1_F LASHTRIGIN/TCPD _CC1_VCONN_EN	GPIO1_A3/ISP 0_FLASHTRIG OUT/ISP1_FLA SHTRIGOUT	GPIO1_A4/ISP 0_PRELIGHT_T RIG/ISP1_PRE LIGHT_TRIG	GPIO0_A1/D DRIO_PWRO FF/TCPD_CC DB_EN	GPIO1_A 5/AP_PW ROFF	GPIO1_B0/S PI1_TXD/UA RT4_TX	R

25	26	27	28	29	30	31	0
NP	NP	NP	NP	NP	NPOR	GPIO1_A1/ISP0_SH UTTER_TRIG/ISP1_ SHUTTER_TRIG/TCP D_CC0_VCONN_EN	T
PMU_VDD_1 V8	SDMMC0_VD DPST	GPIO4_B3/S DMMC0_D3/ APJTAG_TMS	GPIO0_B0/SDM MC0_WRPT/TES T_CLKOUT2	VSS_150	GPIO0_B3	GPIO0_A0/TEST_CL KOUT0/CLK32K_IN	U
GPIO4_B5/S DMMC0_CM D/MCUJTAG _TMS	GPIO0_B4/T CPD_VBUS_ BDIS	GPIO0_A5/E MMC_PWRON	GPIO0_A7/SDM MC0_DET	GPIO4_B4/SD MMC0_CLKOUT /MUCJTAG_TC K	GPIO0_B1/ PMUIO2_V OLSEL	GPIO0_A3/SDIO0_ WRPT	V
NP	NP	NP	NP	NP	VSS_160	GPIO0_B2	W
USB_AVDD_ 3V3	GPIO4_B1/S DMMC0_D1/ UART2A_TX	GPIO4_B0/S DMMC0_D0/ UART2A_RX	GPIO4_B2/SDM MC0_D2/APJTA G_TCK	AVSS_48	XOUT_OSC	XIN_OSC	Y
GPIO0_A4/S DIO0_INTN	AVSS_6	PCIE_TX2_P	PCIE_TX2_N	AVSS_7	USB1_DP	USB1_DN	AA
NP	NP	NP	NP	NP	USB0_DP	USB0_DN	AB
AVSS_51	AVSS_14	PCIE_RX2_P	PCIE_RX2_N	AVSS_15	USB1_RBI AS	USB0_RBIAS	AC

USIC_AVDD_0V9	AVSS_40	PCIE_TX3_P	PCIE_TX3_ N	AVSS_20	PCIE_RCLK_100 M_N	PCIE_RCLK_100 M_P	A D
NP	TYPEC1_ID	AVSS_25	NP	NP	PCIE_TX0_P	PCIE_TX0_N	A E
TYPEC1_AUXM_PU _PD	NP	PCIE_RX3_ P	PCIE_RX3_ N	AVSS_28	PCIE_RX0_P	PCIE_RX0_N	A F
ADC_IN2	ADC_IN0	NP	ADC_IN3	AVSS_29	PCIE_TX1_P	PCIE_TX1_N	A G
NP	ADC_IN1	ADC_IN4	NP	AVSS_30	PCIE_RX1_P	PCIE_RX1_N	A H
NP	VSS_175	VSS_176	VSS_171	AVSS_47	USIC_STROBE	USIC_DATA	AJ
TYPEC1_RX1P	TYPEC1_TX 1M	TYPEC1_RX 2P	TYPEC1_TX 2M	TYPEC1_AU XP	TYPEC0_U2VBUS DET	TYPEC1_U2VBUS DET	A K
TYPEC1_RX1M	TYPEC1_TX 1P	TYPEC1_RX 2M	TYPEC1_TX 2P	TYPEC1_AU XM	TYPEC0_ID	VSS_178	A L
25	26	27	28	29	30	31	

2.5 Ball Pin Number Order

Table 2-1 Ball Pin Number Order Information

PIN#	PIN name	PIN#	PIN name
A1	VSS_1	E23	DDR1_DM3
A2	DDR1_CSN1	E24	VSS_46
A3	DDR1_A12	E25	GPIO3_A3/MAC_RXD3/SPI4_CSN0
A4	DDR1_A10	E26	GPIO3_A6/MAC_RXD0/SPI0_CLK
A5	DDR1_CKE0	E28	GPIO3_C1/MAC_TXCLK/UART3_RTSN
A6	DDR1_A9	E29	GPIO3_B0/MAC_MDC/SPI0_CSN1
A7	DDR1_A7	E30	GPIO3_A2/MAC_RXD2/SPI4_CLK
A8	DDR1_A5	E31	VSS_47
A9	DDR1_A3	F1	DDR0_A1
A10	DDR1_A1	F2	DDR0_A0
A11	DDR1_DQ10	F3	DDR0_RASN
A12	DDR1_DQ12	F4	DDR0_BA1
A13	DDR1_DQ13	F5	DDR0_CKE1
A14	DDR1_DQ14	F7	DDR1_WEN
A15	DDR1_DQ1	F8	VSS_48
A16	DDR1_DQ3	F9	DDR1_CASN
A17	DDR1_DQ5	F11	DDR1_CSN2
A18	DDR1_DQ6	F12	DDR1_CSN0
A19	DDR1_DQ16	F14	DDR1_PLL_TESTOUT_P
A20	DDR1_DQ18	F15	VSS_49
A21	DDR1_DQ20	F17	DDR1_ATB0
A22	DDR1_DQ23	F18	VSS_50
A23	DDR1_DQ24	F20	VSS_51
A24	DDR1_DQ26	F21	VSS_52
A25	DDR1_DQ27	F23	GPIO3_B2/MAC_RXER/I2C5_SDA
A26	DDR1_DQ29	F24	GPIO3_A0/MAC_TXD2/SPI4_RXD
A27	VSS_2	F25	GPIO3_B6/MAC_RXCLK/UART3_RX
A28	EDP_AUXN	F27	GPIO3_A7/MAC_RXD1/SPI0_CSN0
A29	EDP_TX0N	F28	GPIO2_A3/VOP_D3/CIF_D3
A30	EDP_TX1N	F29	GPIO2_A5/VOP_D5/CIF_D5
A31	VSS_3	F30	GPIO2_B1/SPI2_RXD/CIF_HREF/I2C6_SDA
AA1	DDR0_DQ3	F31	GPIO2_B4/SPI2_CSN0
AA2	DDR0_DQ2	G1	DDR0_A2
AA3	VSS_4	G2	DDR0_A3
AA4	DDR0_DQS0N	G5	VSS_53
AA5	VSS_5	G6	DDR0_WEN
AA6	GPIO3_D5/I2S0_SDI2SDO2	G8	DDR1_A15
AA7	GPIO4_A4/I2S1_LRCK_RX	G9	VSS_54
AA8	APIO5_VDDPST	G11	DDR1_RESETN
AA9	VSS_6	G12	DDR1_CLK_VDD
AA10	VSS_179	G14	DDR1_PLL_TESTOUT_N
AA11	AVSS_13	G15	DDR1_PZQ
AA12	AVSS_17	G17	DDR1_ATB1
AA13	VSS_177	G18	VSS_55

PIN#	PIN name	PIN#	PIN name
AA14	AVSS_26	G20	EDP_DC_TP
AA15	AVSS_53	G21	EDP_REXT
AA16	HDMI_AVDD_0V9_1	G23	GPIO3_A5/MAC_TXD1/SPI0_TXD
AA17	HDMI_AVDD_0V9_2	G24	GPIO3_B3/MAC_CLK/I2C5_SCL
AA18	TYPECO_AVDD_1V8	G26	GPIO3_B5/MAC_MDIO/UART1_TX
AA19	NC_8	G27	VSS_56
AA20	NC_9	G30	GPIO2_A7/VOP_D7/CIF_D7/I2C7_SDA
AA21	TYPEC1_AVDD_1V8	G31	GPIO2_A0/VOP_D0/CIF_D0/I2C2_SDA
AA22	NC_11	H1	DDR0_A5
AA23	AVSS_4	H2	DDR0_A4
AA24	DFTJTAG_TMS	H3	VSS_57
AA25	GPIO0_A4/SDIO0_INTN	H4	DDR0_CLK0P
AA26	AVSS_6	H5	DDR0_CLK1P
AA27	PCIE_TX2_P	H6	DDR0_CASN
AA28	PCIE_TX2_N	H7	DDR0_A15
AA29	AVSS_7	H9	VSS_58
AA30	USB1_DP	H10	VSS_59
AA31	USB1_DN	H11	VSS_60
AB1	DDR0_DQ1	H12	VSS_61
AB2	DDR0_DQ0	H13	VSS_62
AB8	APIO3_VDD_1V8	H14	DDR1PLL_AVDD_0V9
AB9	VSS_9	H15	VSS_63
AB10	AVSS_12	H16	VSS_64
AB11	AVSS_8	H17	VSS_65
AB12	MIPI_TX0_AVDD_1V8	H18	VSS_66
AB13	AVSS_9	H19	EDP_AVSS_5
AB14	MIPI_RX0_AVDD_1V8	H20	EDP_AVDD_0V9
AB15	AVSS_42	H21	EDP_CLK24M_IN
AB16	AVSS_41	H22	GPIO3_B4/MAC_TXEN/UART1_RX
AB17	AVSS_52	H23	GPIO3_A1/MAC_TXD3/SPI4_TXD
AB18	TYPECO_AVDD_3V3	H24	GPIO2_B2/SPI2_TXD/CIF_CLKIN/I2C6_SCL
AB19	VSS_140	H25	GPIO2_A1/VOP_D1/CIF_D1/I2C2_SCL
AB20	NC_10	H26	VSS_67
AB21	TYPEC1_AVDD_3V3	H27	GPIO2_A6/VOP_D6/CIF_D6
AB22	NC_1	H28	GPIO2_B0/VOP_CLK/CIF_VSYNC/I2C7_SCL
AB23	AVSS_5	H29	GPIO2_A4/VOP_D4/CIF_D4
AB24	DFTJTAG_TRSTN	H30	GPIO2_A2/VOP_D2/CIF_D2
AB30	USB0_DP	H31	GPIO2_B3/SPI2_CLK/VOP_DEN/CIF_CLKOUT A
AB31	USB0_DN	J1	DDR0_A6
AC1	DDR0_DQ14	J2	DDR0_A7
AC2	DDR0_DQ15	J3	VSS_68
AC3	VSS_16	J4	DDR0_CLK0N
AC4	DDR0_DQS1P	J5	DDR0_CLK1N

PIN#	PIN name	PIN#	PIN name
AC5	DDR0_DM1	J6	VSS_69
AC6	GPIO4_A7/I2S1_SDO0	J7	VSS_70
AC7	GPIO4_A0/I2S_CLK	J8	VSS_71
AC8	APIO4_VDDPST	J9	VSS_72
AC9	APIO4_VDD	J10	VSS_73
AC10	MIPI_TX1/RX1_AVDD_1V8	J11	DDR1_VDD_1
AC11	AVSS_44	J12	DDR1_VDD_2
AC12	NC_7	J13	DDR1_VDD_3
AC13	AVSS_45	J14	DDR1_VDD_4
AC14	NC_4	J15	DDR1_VDD_5
AC15	AVSS_10	J16	DDR1_VDD_6
AC16	AVSS_18	J17	DDR1_VDD_7
AC17	AVSS_43	J18	DDR1_VDD_8
AC18	VSS_145	J19	EDP_AVDD_1V8_1
AC19	TYPE1_U3VBUSDET	J20	EDP_AVDD_1V8_2
AC20	VSS_13	J21	EDP_AVSS_6
AC21	VSS_132	J22	APIO1_VDDPST
AC22	VSS_12	J23	APIO1_VDD
AC23	AVSS_19	J24	APIO2_VDDPST
AC24	ADC_AVDD	J25	EMMC_D3
AC25	AVSS_51	J26	EMMC_D4
AC26	AVSS_14	J27	EMMC_D5
AC27	PCIE_RX2_P	J28	EMMC_D0
AC28	PCIE_RX2_N	J29	EMMC_D1
AC29	AVSS_15	J30	EMMC_D2
AC30	USB1_RBIAS	J31	EMMC_CMD
AC31	USB0_RBIAS	K1	DDR0_A9
AD1	DDR0_DQ13	K2	DDR0_A8
AD2	DDR0_DQ11	K8	VSS_74
AD3	VSS_17	K9	VSS_75
AD4	DDR0_DQS1N	K10	VSS_76
AD5	VSS_18	K11	DDR1_VDD_9
AD6	GPIO4_A6/I2S1_SDI0	K12	VSS_77
AD7	GPIO4_C7/HDMI_CECINOUT/EDP_H OTPLUG	K13	DDR1_VDD_10
AD8	GPIO2_C4/SDIO0_D0/SPI5_RXD	K14	VSS_78
AD9	GPIO2_D3/SDIO0_PWREN	K15	DDR1_VDD_11
AD10	VSS_19	K16	VSS_79
AD11	NC_2	K17	DDR1_VDD_12
AD12	NC_3	K18	VSS_80
AD13	AVSS_11	K19	BIGCPU_VDD_12
AD14	NC_5	K20	VSS_82
AD15	NC_6	K21	BIGCPU_VDD_13
AD16	HDMI_AVDD_1V8	K22	VSS_84

PIN#	PIN name	PIN#	PIN name
AD17	AVSS_16	K23	APIO2_VDD
AD18	TYPEC0_RCLKM	K24	EMMC_VDD_1V8
AD19	TYPEC0_U3VBUSDET	K30	EMMC_D7
AD20	TYPEC1_RCLKM	K31	EMMC_STRB
AD21	VSS_163	L1	DDR0_DQ29
AD22	VSS_11	L2	DDR0_DQ31
AD23	EFUSE	L3	VSS_85
AD24	USIC_AVDD_1V2	L4	DDR0_ODT0
AD25	USIC_AVDD_0V9	L5	DDR0_ODT1
AD26	AVSS_40	L6	VSS_86
AD27	PCIE_TX3_P	L7	DDR0_RESETN
AD28	PCIE_TX3_N	L8	VSS_87
AD29	AVSS_20	L9	DDR0_VDD_1
AD30	PCIE_RCLK_100M_N	L10	DDR0_VDD_2
AD31	PCIE_RCLK_100M_P	L11	VSS_88
AE1	DDR0_DQ12	L12	VSS_89
AE2	DDR0_DQ9	L13	VSS_90
AE5	GPIO3_D4/I2S0_SDI1SDO3	L14	VSS_91
AE6	GPIO4_D0/PCIE_CLKREQNB	L15	VSS_92
AE8	GPIO2_C7/SDIO0_D3/SPI5_CSNO	L16	VSS_93
AE9	GPIO2_C0/UART0_RX	L17	LOGIC_VDD_10
AE11	AVSS_21	L18	BIGCPU_VDD_8
AE12	AVSS_22	L19	BIGCPU_VDD_1
AE14	AVSS_23	L20	VSS_96
AE15	HDMI_HPD	L21	BIGCPU_VDD_2
AE17	AVSS_24	L22	VSS_97
AE18	TYPEC0_RCLKP	L23	BIGCPU_VDD_11
AE20	TYPEC1_RCLKP	L24	EMMC_COREDLL_0V9
AE21	TYPEC1_REXT	L25	GPIO1_C6/TCPD_VBUS_SOURCE0
AE23	VSS_14	L26	GPIO1_D0/TCPD_VBUS_SOURCE2
AE24	TYPEC1_AUXP_PD_PU	L27	VSS_99
AE26	TYPEC1_ID	L28	EMMC_CLK
AE27	AVSS_25	L29	EMMC_CALIO
AE30	PCIE_TX0_P	L30	EMMC_TP
AE31	PCIE_TX0_N	L31	EMMC_D6
AF1	DDR0_DQ10	M1	DDR0_DQ27
AF2	DDR0_DQ8	M2	DDR0_DQ30
AF3	GPIO4_A3/I2S1_SCLK	M3	VSS_100
AF4	GPIO3_D1/I2S0_LRCK_RX	M4	DDR0_BA2
AF5	GPIO4_C2/PWM0/VOP0_PWM/VOP1_PWM	M5	DDR0_CSN2
AF7	GPIO2_D1/SDIO0_CLKOUT/TEST_CLKOUT1	M6	DDR0_CSN0
AF8	GPIO2_D4/SDIO0_BKPWR	M7	DDR0_CLK_VDD

PIN#	PIN name	PIN#	PIN name
AF9	VSS_20	M8	VSS_101
AF11	MIPI_TX1/RX1_REXT	M9	DDR0_VDD_3
AF12	MIPI_TX0_REXT	M10	VSS_102
AF14	MIPI_RX0_REXT	M11	CENTERLOGIC_VDD_1
AF15	HDMI_REXT	M12	CENTERLOGIC_VDD_2
AF17	AVSS_27	M13	CENTERLOGIC_VDD_3
AF18	VSS_7	M14	CENTERLOGIC_VDD_4
AF20	VSS_10	M15	CENTERLOGIC_VDD_5
AF21	TYPEC1_CC2	M16	VSS_103
AF23	AVSS_2	M17	LOGIC_VDD_9
AF24	AVSS_3	M18	BIGCPU_VDD_3
AF25	TYPEC1_AUXM_PU_PD	M19	BIGCPU_VDD_4
AF27	PCIE_RX3_P	M20	BIGCPU_VDD_5
AF28	PCIE_RX3_N	M21	BIGCPU_VDD_6
AF29	AVSS_28	M22	BIGCPU_VDD_7
AF30	PCIE_RX0_P	M23	VSS_104
AF31	PCIE_RX0_N	M24	GPIO1_B5
AG1	GPIO4_A1/I2C1_SDA	M25	GPIO1_B6/PWM3B_IR
AG2	VSS_21	M26	GPIO1_B7/SPI3_RXD/I2C0_SDA
AG3	GPIO3_D0/I2S0_SCLK	M27	GPIO1_C1/SPI3_CLK
AG4	GPIO4_D6	M28	GPIO1_C3/PWM2
AG6	GPIO4_C0/I2C3_SDA/UART2B_RX	M29	GPIO1_C4/I2C8_SDA
AG7	GPIO2_C6/SDIO0_D2/SPI5_CLK	M30	GPIO1_C5/I2C8_SCL
AG8	GPIO2_C2/UART0_CTSN	M31	GPIO1_C7/TCPD_VBUS_SOURCE1
AG9	MIPI_TX0_D3P	N1	DDR0_DQ26
AG11	MIPI_TX0_D2P	N2	DDR0_DQ28
AG12	MIPI_TX0_CLKP	N8	VSS_105
AG14	MIPI_TX0_D1P	N9	DDR0_VDD_4
AG15	MIPI_TX0_D0P	N10	DDR0_VDD_5
AG17	TYPEC0_AUXM_PU_PD	N11	CENTERLOGIC_VDD_6
AG18	TYPEC0_REXT	N12	CENTERLOGIC_VDD_7
AG20	TYPEC0_REXT_CC	N13	VSS_108
AG21	TYPEC1_REXT_CC	N14	VSS_109
AG23	TYPEC0_DP	N15	VSS_110
AG24	TYPEC1_DP	N16	VSS_111
AG25	ADC_IN2	N17	VSS_94
AG26	ADC_IN0	N18	BIGCPU_VDD_COM
AG28	ADC_IN3	N19	VSS_83
AG29	AVSS_29	N20	BIGCPU_VDD_10
AG30	PCIE_TX1_P	N21	VSS_98
AG31	PCIE_TX1_N	N22	BIGCPU_VDD_9
AH1	GPIO3_D7/I2S0_SDO0	N23	PMUIO2_VDDPST
AH2	GPIO3_D6/I2S0_SDI3SDO1	N24	GPIO0_A2/WIFI_26MHZ
AH3	GPIO4_D2	N30	GPIO1_C0/SPI3_TXD/I2C0_SCL

PIN#	PIN name	PIN#	PIN name
AH5	GPIO4_D4	N31	GPIO1_C2/SPI3_CSN0
AH6	GPIO2_D0/SDIO0_CMD	P1	DDR0_DQ24
AH8	GPIO2_C1/UART0_TX	P2	DDR0_DQ25
AH9	MIPI_TX0_D3N	P3	VSS_112
AH11	MIPI_TX0_D2N	P4	DDR0_DQS3P
AH12	MIPI_TX0_CLKN	P5	DDR0_DM3
AH14	MIPI_TX0_D1N	P6	VSS_113
AH15	MIPI_TX0_D0N	P7	VSS_114
AH17	TYPECO_AUXP_PD_PU	P8	VSS_115
AH18	TYPECO_CC1	P9	DDR0_VDD_6
AH20	TYPECO_CC2	P10	VSS_116
AH21	TYPECO1_CC1	P11	VSS_106
AH23	TYPECO_DN	P12	VSS_107
AH24	TYPECO1_DN	P13	CENTERLOGIC_VDD_8
AH26	ADC_IN1	P14	CENTERLOGIC_VDD_9
AH27	ADC_IN4	P15	CENTERLOGIC_VDD_10
AH29	AVSS_30	P16	VSS_117
AH30	PCIE_RX1_P	P17	PLL_AVSS
AH31	PCIE_RX1_N	P18	PLL_AVDD_1V8
AJ1	GPIO4_A5/I2S1_LRCK_TX	P19	VSS_119
AJ2	GPIO3_D2/I2S0_LRCK_TX	P20	LITCPU_VDD_1
AJ3	GPIO4_D5	P21	VSS_121
AJ4	GPIO4_C4/UART2C_TX	P22	LITCPU_VDD_4
AJ5	VSS_22	P23	PMUIO2_VDD
AJ6	AVSS_31	P24	GPIO0_B5/TCPD_VBUS_FDIS/TCPD_VBUS_S OURCE3
AJ8	AVSS_32	P25	GPIO0_A6/PWM3A_IR
AJ9	AVSS_33	P26	GPIO1_A6/TSADC_INT
AJ11	AVSS_34	P27	GPIO1_A7/SPI1_RXD/UART4_RX
AJ12	AVSS_35	P28	GPIO1_B1/SPI1_CLK/PMCU_JTAG_TCK
AJ14	AVSS_36	P29	GPIO1_B2/SPI1_CSN0/PMCU_JTAG_TMS
AJ15	AVSS_37	P30	GPIO1_B4/I2C4_SCL
AJ17	AVSS_38	P31	GPIO1_B3/I2C4_SDA
AJ18	AVSS_39	R1	DDR0_DQ23
AJ20	VSS_180	R2	DDR0_DQ22
AJ21	VSS_172	R3	VSS_123
AJ23	VSS_173	R4	DDR0_DQS3N
AJ24	VSS_174	R5	VSS_124
AJ26	VSS_175	R6	VSS_125
AJ27	VSS_176	R7	DDR0_PZQ
AJ28	VSS_171	R8	DDR0PLL_AVDD_0V9
AJ29	AVSS_47	R9	DDR0_VDD_7
AJ30	USIC_STROBE	R10	DDR0_VDD_8
AJ31	USIC_DATA	R11	GPU_VDD_8

PIN#	PIN name	PIN#	PIN name
AK1	GPIO4_C5/SPDIF_TX	R12	GPU_VDD_9
AK2	GPIO4_C3/UART2C_RX	R13	GPU_VDD_13
AK3	GPIO4_D3	R14	VSS_129
AK4	GPIO4_D1/DP_HOTPLUG	R15	VSS_130
AK5	GPIO2_C5/SDIO0_D1/SPI5_TXD	R16	VSS_131
AK6	MIPI_TX1/RX1_D0P	R17	PLL_AVDD_0V9
AK7	MIPI_TX1/RX1_D1P	R18	VSS_165
AK8	MIPI_TX1/RX1_CLKP	R19	LITCPU_VDD_2
AK9	MIPI_TX1/RX1_D2P	R20	LITCPU_VDD_3
AK10	MIPI_TX1/RX1_D3P	R21	VSS_120
AK11	MIPI_RX0_D3P	R22	LITCPU_VDD_7
AK12	MIPI_RX0_D2P	R23	VSS_133
AK13	MIPI_RX0_CLKP	R24	PMUIO1_VDD_1V8
AK14	MIPI_RX0_D1P	R25	GPIO1_A0/ISP0_SHUTTER_EN/ISP1_SHUTTE R_EN/TCPD_VBUS_SINK_EN
AK15	MIPI_RX0_D0P	R26	GPIO1_A2/ISP0_FLASHTRIGIN/ISP1_FLASHT RIGIN/TCPD_CC1_VCONN_EN
AK16	HDMI_TCP	R27	GPIO1_A3/ISP0_FLASHTRIGOUT/ISP1_FLAS HTRIGOUT
AK17	HDMI_TX0P	R28	GPIO1_A4/ISP0_PRELIGHT_TRIG/ISP1_PREL IGHT_TRIG
AK18	HDMI_TX1P	R29	GPIO0_A1/DDRIO_PWROFF/TCPD_CCDB_EN
AK19	HDMI_TX2P	R30	GPIO1_A5/AP_PWROFF
AK20	TYPECO_AUXP	R31	GPIO1_B0/SPI1_TXD/UART4_TX
AK21	TYPECO_RX1P	T1	DDR0_DQ20
AK22	TYPECO_TX1M	T2	DDR0_DQ21
AK23	TYPECO_RX2P	T8	VSS_134
AK24	TYPECO_TX2M	T9	DDR0_VDD_9
AK25	TYPECE1_RX1P	T10	VSS_135
AK26	TYPECE1_TX1M	T11	GPU_VDD_10
AK27	TYPECE1_RX2P	T12	GPU_VDD_11
AK28	TYPECE1_TX2M	T13	GPU_VDD_12
AK29	TYPECE1_AUXP	T14	GPU_VDD_14
AK30	TYPECO_U2VBUSDET	T15	GPU_VDD_COM
AK31	TYPECE1_U2VBUSDET	T16	VSS_138
AL1	VSS_23	T17	LOGIC_VDD_11
AL2	GPIO4_C1/I2C3_SCL/UART2B_TX	T18	VSS_168
AL3	GPIO4_C6/PWM1	T19	VSS_122
AL4	GPIO2_D2/SDIO0_DET/PCIE_CLKR EQN	T20	LITCPU_VDD_6
AL5	GPIO2_C3/UART0_RTSN	T21	VSS_139
AL6	MIPI_TX1/RX1_D0N	T22	LITCPU_VDD_5
AL7	MIPI_TX1/RX1_D1N	T23	SDMMC0_VDD
AL8	MIPI_TX1/RX1_CLKN	T24	PMU_VDD_0V9
AL9	MIPI_TX1/RX1_D2N	T30	NPOR

PIN#	PIN name	PIN#	PIN name
AL10	MIPI_TX1/RX1_D3N	T31	GPIO1_A1/ISP0_SHUTTER_TRIG/ISP1_SHUTTER_TRIG/TCPD_CC0_VCONN_EN
AL11	MIPI_RX0_D3N	U1	DDR0_DQ18
AL12	MIPI_RX0_D2N	U2	DDR0_DQ19
AL13	MIPI_RX0_CLKN	U3	VSS_141
AL14	MIPI_RX0_D1N	U4	DDR0_DQS2P
AL15	MIPI_RX0_D0N	U5	DDR0_DM2
AL16	HDMI_TCN	U6	DDR0_ATB0
AL17	HDMI_TX0N	U7	DDR0_ATB1
AL18	HDMI_TX1N	U8	VSS_142
AL19	HDMI_TX2N	U9	DDR0_VDD_10
AL20	TYPECO_AUXM	U10	DDR0_VDD_11
AL21	TYPECO_RX1M	U11	VSS_126
AL22	TYPECO_TX1P	U12	VSS_127
AL23	TYPECO_RX2M	U13	GPU_VDD_7
AL24	TYPECO_TX2P	U14	VSS_137
AL25	TYPEC1_RX1M	U15	VSS_143
AL26	TYPEC1_TX1P	U16	VSS_144
AL27	TYPEC1_RX2M	U17	LOGIC_VDD_8
AL28	TYPEC1_TX2P	U18	LOGIC_VDD_7
AL29	TYPEC1_AUXM	U19	VSS_146
AL30	TYPECO_ID	U20	LOGIC_VDD_12
AL31	VSS_178	U21	VSS_147
B1	DDR0_CSN1	U22	VSS_149
B2	DDR1_BA0	U23	AVSS_49
B3	DDR1_CSN3	U24	USB_AVDD_1V8
B4	DDR1_A13	U25	PMU_VDD_1V8
B5	VSS_24	U26	SDMMC0_VDDPST
B6	DDR1_A8	U27	GPIO4_B3/SDMMC0_D3/APJTAG_TMS
B7	DDR1_A6	U28	GPIO0_B0/SDMMC0_WRPT/TEST_CLKOUT2
B8	DDR1_A4	U29	VSS_150
B9	DDR1_A2	U30	GPIO0_B3
B10	DDR1_A0	U31	GPIO0_A0/TEST_CLKOUT0/CLK32K_IN
B11	DDR1_DQ8	V1	DDR0_DQ16
B12	DDR1_DQ9	V2	DDR0_DQ17
B13	DDR1_DQ11	V3	VSS_151
B14	DDR1_DQ15	V4	DDR0_DQS2N
B15	DDR1_DQ0	V5	VSS_152
B16	DDR1_DQ2	V6	DDR0_PLL_TESTOUT_P
B17	DDR1_DQ4	V7	DDR0_PLL_TESTOUT_N
B18	DDR1_DQ7	V8	VSS_153
B19	DDR1_DQ17	V9	DDR0_VDD_12
B20	DDR1_DQ19	V10	VSS_154
B21	DDR1_DQ21	V11	GPU_VDD_15

PIN#	PIN name	PIN#	PIN name
B22	DDR1_DQ22	V12	GPU_VDD_16
B23	DDR1_DQ25	V13	GPU_VDD_6
B24	DDR1_DQ28	V14	GPU_VDD_5
B25	DDR1_DQ30	V15	GPU_VDD_4
B26	DDR1_DQ31	V16	GPU_VDD_17
B27	GPIO3_B7/MAC_CRS/UART3_TX/CIF_CLKOUTB	V17	VSS_148
B28	EDP_AUXP	V18	LOGIC_VDD_5
B29	EDP_TX0P	V19	LOGIC_VDD_4
B30	EDP_TX1P	V20	LOGIC_VDD_3
B31	EDP_AVSS_1	V21	LOGIC_VDD_2
C1	DDR0_A12	V22	LOGIC_VDD_1
C2	DDR0_CSN3	V23	AVSS_50
C3	DDR0_BA0	V24	USB_AVDD_0V9
C4	DDR1_A14	V25	GPIO4_B5/SDMMC0_CMD/MCUJTAG_TMS
C5	DDR1_A11	V26	GPIO0_B4/TCPD_VBUS_BDIS
C6	DDR1_RASN	V27	GPIO0_A5/EMMC_PWRON
C8	VSS_25	V28	GPIO0_A7/SDMMC0_DET
C9	VSS_26	V29	GPIO4_B4/SDMMC0_CLKOUT/MUCJTAG_TCK
C11	VSS_27	V30	GPIO0_B1/PMUIO2_VOLSEL
C12	VSS_28	V31	GPIO0_A3/SDIO0_WRPT
C14	VSS_29	W1	DDR0_DQ6
C15	VSS_30	W2	DDR0_DQ7
C17	VSS_31	W8	VSS_161
C18	VSS_32	W9	VSS_162
C20	VSS_33	W10	GPU_VDD_20
C21	VSS_34	W11	GPU_VDD_1
C23	VSS_35	W12	GPU_VDD_2
C24	VSS_36	W13	VSS_128
C26	VSS_37	W14	GPU_VDD_3
C27	GPIO3_B1/MAC_RXDV	W15	GPU_VDD_19
C28	EDP_AVSS_2	W16	GPU_VDD_18
C29	EDP_AVSS_3	W17	VSS_159
C30	EDP_TX2P	W18	VSS_169
C31	EDP_TX2N	W19	VSS_167
D1	DDR0_A10	W20	LOGIC_VDD_6
D2	DDR0_A13	W21	VSS_81
D3	DDR0_A14	W22	VSS_158
D5	VSS_38	W23	AVSS_46
D6	DDR1_BA1	W24	PCIE_AVDD_0V9
D8	DDR1_CLK0N	W30	VSS_160
D9	DDR1_CLK0P	W31	GPIO0_B2
D11	DDR1_ODT0	Y1	DDR0_DQ5
D12	DDR1_BA2	Y2	DDR0_DQ4

PIN#	PIN name	PIN#	PIN name
D14	DDR1_DQS1N	Y3	VSS_8
D15	DDR1_DQS1P	Y4	DDR0_DQS0P
D17	DDR1_DQS0N	Y5	DDR0_DM0
D18	DDR1_DQS0P	Y6	GPIO4_A2/I2C1_SCL
D20	DDR1_DQS2N	Y7	GPIO3_D3/I2S0_SDI0
D21	DDR1_DQS2P	Y8	API05_VDD
D23	DDR1_DQS3N	Y9	VSS_166
D24	DDR1_DQS3P	Y10	VSS_15
D26	GPIO3_A4/MAC_TXD0/SPI0_RXD	Y11	VSS_155
D27	GPIO3_C0/MAC_COL/UART3_CTSN/ SPDIF_TX	Y12	VSS_136
D29	EDP_AVSS_4	Y13	VSS_164
D30	EDP_TX3P	Y14	VSS_156
D31	EDP_TX3N	Y15	VSS_157
E1	DDR0_CKE0	Y16	VSS_118
E2	VSS_39	Y17	VSS_95
E3	DDR0_A11	Y18	TYPEC0_AVDD_0V9_2
E4	VSS_40	Y19	TYPEC0_AVDD_0V9_1
E6	DDR1_CKE1	Y20	VSS_170
E7	VSS_41	Y21	TYPEC1_AVDD_0V9_1
E8	DDR1_CLK1N	Y22	TYPEC1_AVDD_0V9_2
E9	DDR1_CLK1P	Y23	AVSS_1
E11	DDR1_ODT1	Y24	PCIE_AVDD_1V8
E12	VSS_42	Y25	USB_AVDD_3V3
E14	DDR1_DM1	Y26	GPIO4_B1/SDMMC0_D1/UART2A_TX
E15	VSS_43	Y27	GPIO4_B0/SDMMC0_D0/UART2A_RX
E17	DDR1_DM0	Y28	GPIO4_B2/SDMMC0_D2/APJTAG_TCK
E18	VSS_44	Y29	AVSS_48
E20	DDR1_DM2	Y30	XOUT_OSC
E21	VSS_45	Y31	XIN_OSC

2.6 Power/ground IO descriptions

Table 2-2 Power/Ground IO information

Group	Ball #	Descriptions
VSS	A1,A27,A31,AA3,AA5,AA9,AA10,AA13,AB9,AB19,AC3,AC18,AC20,AC21,AC22,AD3,AD5,AD10,AD21,AD22,AE23,AF9,AF18,AF20,AG2,AJ5,AJ20,AJ21,AJ23,AJ24,AJ26,AJ27,AJ28,AL1,AL31,B5,C8,C9,C11,C12,C14,C15,C17,C18,C20,C21,C23,C24,C26,D5,E2,E4,E7,E12,E15,E18,E21,E24,E31,F8,F15,F18,F20,F21,G5,G9,G18,G27,H3,H9,H10,H11,H12,H13,H15,H16,H17,H18,H26,J3,J6,J7,J8,J9,J10,K8,K9,K10,K12,K14,K16,K18,K20,K22,L3,L6,L8,L11,L12,L13,L14,L15,L16,L20,L22,L27,M3,M8,M10,M16,M23,N8,N13,N14,N15,N16,N17,N19,N21,P3,P6,P7,P8,P10,P11,P12,P16,P19,P2	Internal Logic Ground and Digital IO Ground

Group	Ball #	Descriptions
	1,R3,R5,R6,R14,R15,R16,R18,R21,R23,T8,T10,T16,T18,T19,T21,U3,U8,U11,U12,U14,U15,U16,U19,U21,U22,U29,V3,V5,V8,V10,V17,W8,W9,W13,W17,W18,W19,W21,W22,W30,Y3,Y9,Y10,Y11,Y12,Y13,Y14,Y15,Y16,Y17,Y20	
BIGCPU_VDD	K19,K21,L18,L19,L21,L23,M18,M19,M20,M21,M22,N18,N20,N22	Internal BIG CPU A72 Power
LITCPU_VDD	P20,P22,R19,R20,R22,T20,T22	Internal LITTLE CPU A53 Power
GPU_VDD	R11,R12,R13,T11,T12,T13,T14,T15,U13,V11,V12,V13,V14,V15,V16,W10,W11,W12,W14,W15,W16	Internal GPU power
LOGIC_VDD	L17,M17,T17,U17,U18,U20,V18,V19,V20,V21,V22,W20	Internal Logic Power
CENTERLOGIC_VDD	M11,M12,M13,M14,M15,N11,N12,P13,P14,P15	Internal center logic power
DDR0_VDD	L9,L10,M9,N9,N10,P9,R9,R10,T9,U9,U10,V9	DDR0 Digital IO Power
DDR0_CLK_VDD	M7	DDR0Clock IO Power
DDR0PLL_AVDD_0V9	R8	DDR0 PHY PLL power
DDR1_VDD	J11,J12,J13,J14,J15,J16,J17,J18,K11,K13,K15,K17	DDR1 Digital IO Power
DDR1_CLK_VDD	G12	DDR1 Clock IO Power
DDR1PLL_AVDD_0V9	H14	DDR1 PHY PLL power
PMU_VDD_0V9	T24	Internal PMU Domain Power
PMU_VDD_1V8	U25	
PMUIO1_VDD	R24	PMUIO1 Domain IO Power
PMUIO2_VDD	P23 N23	PMUIO2 Domain IO Power
APIO1_VDD	J23	GPIO group 1 Digital Power
APIO1_VDDPST	K23	GPIO group 1Bias
APIO2_VDD	L23 J22	GPIO group 2 Digital Power
APIO2_VDDPST	J24	GPIO group 2 Bias
APIO3_VDD	AB8	GPIO group 3 Digital Power
APIO4_VDD	AC9	GPIO group 4 Digital Power
APIO4_VDDPST	AC8	GPIO group 4Bias
APIO5_VDD	Y8	GPIO group 5 Digital Power
APIO5_VDDPST	AA8	GPIO group 5Bias
SDMMC0_VDD	T23, U26	SDMMC Digital IO Power
AVSS	AA11,AA12,AA14,AA15,AA23,AA26,AA29,AB10,AB11,AB13,AB15,AB16,AB17,AB23,AC11,AC13,AC15,AC16,AC17,AC23,AC25,AC26,AC29,AD13,AD17,AD26,AD29,AE11,AE12,AE14,AE17,AE27,AF17,AF23,AF24,AF29,AG29,AH29,AJ6,AJ8,AJ9,AJ11,AJ12,AJ14,AJ15,AJ17,AJ18,AJ29,B31,C28,C29,D29,H19,J21,U23,V23,W23,Y23,Y29	Analog Ground
PLL_AVDD_0V9	R17	PLL 0.9V Analog Power
PLL_AVDD_1V8	P18	PLL 1.8V Analog Power
PLL_AVSS	P17	PLL Analog Ground
ADC_AVDD	AC24	SAR-ADC/TSADC Power

Group	Ball #	Descriptions
EMMC_VDD_1V8	K24	eMMC digital power
EMMC_COREDLL_0V9	L24	eMMC core digital power
USB_AVDD_0V9	V24	USB 2.0 Digital Power
USB_AVDD_1V8	U24	USB 2.0 Analog Power
USB_AVDD_3V3	Y25	USB 2.0 Analog Power
TYPEC0_AVDD_0V9	Y18,Y19	Type-C Digital Power
TYPEC0_AVDD_1V8	AA18	Type-C Analog Power
TYPEC0_AVDD_3V3	AB18	Type-C Analog Power
TYPEC1_AVDD_0V9	Y21,Y22	Type-C Digital Power
TYPEC1_AVDD_1V8	AA21	Type-C Analog Power
TYPEC1_AVDD_3V3	AB21	Type-C Analog Power
EFUSE	AD23	eFuse IO Digital Power
USIC_AVDD_1V2	AD24	USIC 1.2V Power Supply
USIC_AVDD_0V9	AD25	USIC 0.9V Power Supply
EDP_AVDD_0V9	H20	eDP0.9V Power Supply
EDP_AVDD_1V8	J19,J20	eDP 1.8V Power Supply
EDP_AVSS	B31,C28,C29,D29,H19,J21	eDP analog ground
HDMI_AVDD_0V9	AA16,AA17	HDMI 0.9V Power Supply
HDMI_AVDD_1V8	AD16	HDMI 1.8V Power Supply
MIPI_AVDD_1V8	AB14 AB12 AC10	MIPI 1.8V Power Supply
PCIE_AVDD_0V9	W24	PCIE 0.9V analog power
PCIE_AVDD_1V8	Y24	PCIE 1.8V analog power

2.7 Power supply for IO

- PMUIO1 IO domain
 - Only support 1.8v mode, with PMUIO1_VDD_1V8(1.8v typical) power supply.
- PMUIO2 IO domain
 - Support 1.8v and 3.0v mode, controlled by PMUGRF_SOC_CON0[9:8], please refer to GRF TRM chapter for detail control information description.
 - With PMUIO2_VDDPST and PMUIO2_VDD two power supply.
 - ◆ 1.8v mode: Both PMUIO2_VDDPST and PMUIO2_VDD power supply with 1.8v(typical).
 - ◆ 3.0v mode: PMUIO2_VDDPST power supply with 1.5v(typical) and PMUIO2_VDD power supply with 3.0v(typical).
 - PMUIO2_VDDPST and PMUIO2_VDD power up rise time need to >100us and power down fall time also need to >100us.
 - Change from 3.0v mode to 1.8v mode sequence: change external power supply firstly, then wait >1ms, last configure GFR register to change IO working mode.

- Change from 1.8v mode to 3.0v mode sequence: configure GFR register to change IO working mode firstly, then wait >1ms, last change external power supply.
- Power up sequence for 3.0v mode: power up PMUIO2_VDDPST firstly, then wait >20us, last power up PMUIO2_VDD.
- Power down sequence for 3.0v mode: power down PMUIO2_VDD firstly, then wait >20us, last power down PMUIO2_VDDPST.
- Not support fail-safe condition (PMUIO2 power off, but signal PAD still with high level input drive), otherwise IO reliability will be uncontrollable.
- APIO1 IO domain
 - Only support 3.3v mode, with APIO1_VDDPST(1.8v typical) and APIO1_VDD(3.3v typical) two power supply.
 - APIO1_VDDPST and APIO1_VDD power up rise time need to >100us and power down fall time also need to >100us.
 - Power up sequence: power up APIO1_VDDPST firstly, then wait >20us, last power up APIO1_VDD.
 - Power down sequence: power down APIO1_VDD firstly, then wait >20us, last power down APIO1_VDDPST.
 - Not support fail-safe condition (APIO1 power off, but signal PAD still with high level input drive), otherwise IO reliability will be uncontrollable.
- APIO2/4/5 IO domain
 - Support 1.8v and 3.0v mode, controlled by GRF_IO_VSEL, please refer to GRF TRM chapter for detail control information description.
 - With APIO2/4/5_VDDPST and APIO2/4/5_VDD two power supply.
 - ◆ 1.8v mode: Both APIO2/4/5_VDDPST and APIO2/4/5_VDD power supply with 1.8v(typical).
 - ◆ 3.0v mode: APIO2/4/5_VDDPST power supply with 1.5v(typical) and APIO2/4/5_VDD power supply with 3.0v(typical).
 - APIO2/4/5_VDDPST and APIO2/4/5_VDD power up rise time need to >100us and power down fall time also need to >100us.
 - Change from 3.0v mode to 1.8v mode sequence: change external power supply firstly, then wait >1ms, last configure GFR register to change IO working mode.
 - Change from 1.8v mode to 3.0v mode sequence: configure GFR register to change IO working mode firstly, then wait >1ms, last change external power supply.
 - Power up sequence for 3.0v mode: power up APIO2/4/5_VDDPST firstly, then wait >20us, last power up APIO2/4/5_VDD.
 - Power down sequence for 3.0v mode: power down APIO2/4/5_VDD firstly, then wait >20us, last power down APIO2/4/5_VDDPST.
 - Not support fail-safe condition (APIO2/4/5 power off, but signal PAD still with high level input drive), otherwise IO reliability will be uncontrollable.
- APIO3 IO domain
 - Only support 1.8v mode, with APIO3_VDD_1V8(1.8v typical) power supply.

- SDMMC IO domain
 - Support 1.8v and 3.0v mode, controlled by GRF_IO_VSEL, please refer to GRF TRM chapter for detail control information description.
 - With only SDMMC0_VDD one power supply.
 - ◆ 1.8v mode: SDMMC0_VDD power supply with 1.8v(typical).
 - ◆ 3.0v mode: SDMMC0_VDD power supply with 3.0v(typical).
 - SDMMC0_VDD power up rise time need to >100us and power down fall time also need to >100us.
 - Change from 3.0v mode to 1.8v mode sequence: change external power supply firstly, then wait >1ms, last configure GRF register to change IO working mode.
 - Change from 1.8v mode to 3.0v mode sequence: configure GFR register to change IO working mode firstly, then wait >1ms, last change external power supply.
 - Not support fail-safe condition (SDMMC power off, but signal PAD still with high level input drive), otherwise IO reliability will be uncontrollable.

2.8 Function IO description

Table 2-3 Function IO description

Pin Name	Func 1	Func 2	Func 3	Func 4	Type	Def	PD/PU	Default	INT
GPIO0_A0/TESTCLKOUT0/CLK32K_IN	gpio0_a[0]	testclkout0	clk32k_in		I/O	I	up	5mA	✓
GPIO0_A1/DDRIO_PWROFF/TCPD_CCDB_EN	gpio0_a[1]	ddrio_pwroff	tcpd_ccdb_en		I/O	I	up	5mA	✓
GPIO0_A2/WIFI_26MHZ	gpio0_a[2]	wifi_26m			I/O	I	down	5mA	✓
GPIO0_A3/SDIO0_WRPRT	gpio0_a[3]	sdio0_wrpt			I/O	I	down	5mA	✓
GPIO0_A4/SDIO0_INTN	gpio0_a[4]	sdio0_intn			I/O	I	down	5mA	✓
GPIO0_A5/EMMC_PWRON	gpio0_a[5]	emmc_pwren			I/O	I	up	5mA	✓
GPIO0_A6/PWMA3_IR	gpio0_a[6]	pwma3_ir			I/O	I	down	5mA	✓
GPIO0_A7/SDMMC0_DET	gpio0_a[7]	sdmmc0_dectn			I/O	I	up	5mA	✓
GPIO0_B0/SDMMC0_WRPRT/TEST_CLKOUT2	gpio0_b[0]	sdmmc0_wrprt	test_clkout2		I/O	I	up	5mA	✓
GPIO0_B1/PMUIO2_1833_VOLSEL	gpio0_b[1]	pmuio2_1833_volsel			I/O	I	down	5mA	✓
GPIO0_B2	gpio0_b[2]				I/O	I	down	5mA	✓
GPIO0_B3	gpio0_b[3]				I/O	I	down	5mA	✓
GPIO0_B4/TCPD_VBUS_BDIS	gpio0_b[4]	tcpd_vbus_bdis			I/O	I	down	5mA	✓
GPIO0_B5/TCPD_VBUS_FDIS/TCPD_VBUS_SOURCE3	gpio0_b[5]	tcpd_vbus_fdis	tcpd_vbus_source3		I/O	I	down	5mA	✓
GPIO1_A0/ISP_SHUTTER_EN/TCPD_VBUS_SINK_EN	gpio1_a[0]	isp0_shutter_en	isp1_shutter_en	tcpd_vbus_sink_en	I/O	I	down	3mA	✓
GPIO1_A1/ISP_SHUTTER_TRIG/TCPD_CC0_VCONN_EN	gpio1_a[1]	isp0_shutter_trig	isp1_shutter_trig	tcpd_cc0_vconn_en	I/O	I	down	3mA	✓
GPIO1_A2/ISP_FLASHTRIGIN/TCPD_CC1_VCONN_EN	gpio1_a[2]	isp0_flashtrigin	isp1_flashtrigin	tcpd_cc1_vconn_en	I/O	I	down	3mA	✓
GPIO1_A3/ISP_FLASHTRIGOUT	gpio1_a[3]	isp0_flashtrigout	isp1_flashtrigout		I/O	I	down	3mA	✓
GPIO1_A4/ISP_PRELIGHT_TRIG	gpio1_a[4]	isp0_prelight_trig	isp1_prelight_trig		I/O	I	down	3mA	✓
GPIO1_A5/AP_PWROFF	gpio1_a[5]	ap_pwroff			I/O	I	down	3mA	✓
GPIO1_A6/TSADC_INT	gpio1_a[6]	tsadc_int			I/O	I	high-z	3mA	✓
GPIO1_A7/PMCU_UART4DBG_RX/SPI1_RXD	gpio1_a[7]	pmcu_uart4dbg_rx	spi1_rxd		I/O	I	up	6mA	✓
GPIO1_B0/PMCU_UART4DBG_TX/SPI1_TXD	gpio1_b[0]	pmcu_uart4dbg_tx	spi1_txd		I/O	I	up	6mA	✓

Pin Name	Func 1	Func 2	Func 3	Func 4	Type	Def	PD/PU	Default	INT
GPIO1_B1/SPI1_CLK/PMCU_JTAG_TCK	gpio1_b[1]	pmcu_jtag_tck	spi1_clk		I/O	I	up	6mA	✓
GPIO1_B2/SPI1_CSN0/PMCU_JTAG_TMS	gpio1_b[2]	pmcu_jtag_tms	spi1_csn0		I/O	I	up	6mA	✓
GPIO1_B3/I2C4_SDA	gpio1_b[3]	i2c4_sda			I/O	I	up	3mA	✓
GPIO1_B4/I2C4_SCL	gpio1_b[4]	i2c4_scl			I/O	I	up	3mA	✓
GPIO1_B5	gpio1_b[5]				I/O	I	down	3mA	✓
GPIO1_B6/PWMB3_IR	gpio1_b[6]	pwmb3_ir			I/O	I	down	3mA	✓
GPIO1_B7/SPI3_RXD/I2C0_SDA	gpio1_b[7]	spi3_rxd	i2c0_sda		I/O	I	up	3mA	✓
GPIO1_C0/SPI3_TXD/I2C0_SCL	gpio1_c[0]	spi3_txd	i2c0_scl		I/O	I	up	3mA	✓
GPIO1_C1/SPI3_CLK	gpio1_c[1]	spi3_clk			I/O	I	down	3mA	✓
GPIO1_C2/SPI3_CSN0	gpio1_c[2]	spi3_csn0			I/O	I	up	3mA	✓
GPIO1_C3/PWM2	gpio1_c[3]	pwm2			I/O	I	down	3mA	✓
GPIO1_C4/I2C8_SDA	gpio1_c[4]	i2c8_sda			I/O	I	up	3mA	✓
GPIO1_C5/I2C8_SCL	gpio1_c[5]	i2c8_scl			I/O	I	up	3mA	✓
GPIO1_C6/DFTJTAG_TDI/TCPD_VBUS_SOURCE0	gpio1_c[6]	dftjtag_tdi	tcpd_vbus_source0		I/O	I	down	6mA	✓
GPIO1_C7/DFTJTAG_TDO/TCPD_VBUS_SOURCE1	gpio1_c[7]	dftjtag_tdo	tcpd_vbus_source1		I/O	I	down	6mA	✓
GPIO1_D0/DFTJTAG_CLK/TCPD_VBUS_SOURCE2	gpio1_d[0]	dftjtag_clk	tcpd_vbus_source2		I/O	I	down	6mA	✓
GPIO2_A0/VOP_D0/CIF_D0/I2C2_SDA	gpio2_a[0]	vop_data[0]	io_cif_data0	i2c2_sda	I/O	I	up	3mA	✓
GPIO2_A1/VOP_D1/CIF_D1/I2C2_SCL	gpio2_a[1]	vop_data[1]	io_cif_data1	i2c2_scl	I/O	I	up	3mA	✓
GPIO2_A2/VOP_D2/CIF_D2	gpio2_a[2]	vop_data[2]	io_cif_data2		I/O	I	down	3mA	✓
GPIO2_A3/VOP_D3/CIF_D3	gpio2_a[3]	vop_data[3]	io_cif_data3		I/O	I	down	3mA	✓
GPIO2_A4/VOP_D4/CIF_D4	gpio2_a[4]	vop_data[4]	io_cif_data4		I/O	I	down	3mA	✓
GPIO2_A5/VOP_D5/CIF_D5	gpio2_a[5]	vop_data[5]	io_cif_data5		I/O	I	down	3mA	✓
GPIO2_A6/VOP_D6/CIF_D6	gpio2_a[6]	vop_data[6]	io_cif_data6		I/O	I	down	3mA	✓
GPIO2_A7/VOP_D7/CIF_D7/I2C7_SDA	gpio2_a[7]	vop_data[7]	io_cif_data7	i2c7_sda	I/O	I	up	3mA	✓
GPIO2_B0/VOP_CLK/CIF_VSYNC/I2C7_SCL	gpio2_b[0]	vop_clk	io_cif_vsync	i2c7_scl	I/O	I	up	3mA	✓
GPIO2_B1/SPI2_RXD/CIF_HREF/I2C6_SDA	gpio2_b[1]	spi2_rxd	io_cif_href	i2c6_sda	I/O	I	up	3mA	✓

Pin Name	Func 1	Func 2	Func 3	Func 4	Type	Def	PD/PU	Default	INT
GPIO2_B2/SPI2_TXD/CIF_CLKIN/I2C6_SCL	gpio2_b[2]	spi2_txd	io_cif_clkln	i2c6_scl	I/O	I	up	3mA	✓
GPIO2_B3/SPI2_CLK/VOP_DEN/CIF_CLKOUT	gpio2_b[3]	spi2_clk	io_cif_clkout	vop_den	I/O	I	up	3mA	✓
GPIO2_B4/SPI2_CSN0	gpio2_b[4]	spi2_csn0			I/O	I	up	3mA	✓
GPIO2_C0/UART0_RX	gpio2_c[0]	uart0_rx			I/O	I	up	5mA	✓
GPIO2_C1/UART0_TX	gpio2_c[1]	uart0_tx			I/O	I	up	5mA	✓
GPIO2_C2/UART0_CTSN	gpio2_c[2]	uart0_ctsn			I/O	I	up	5mA	✓
GPIO2_C3/UART0_RTSN	gpio2_c[3]	uart0_rtsn			I/O	I	up	5mA	✓
GPIO2_C4/SDIO0_D0/SPI5_RXD	gpio2_c[4]	sdio0_data0	spi5_rxd		I/O	I	up	5mA	✓
GPIO2_C5/SDIO0_D1/SPI5_TXD	gpio2_c[5]	sdio0_data1	spi5_txd		I/O	I	up	5mA	✓
GPIO2_C6/SDIO0_D2/SPI5_CLK	gpio2_c[6]	sdio0_data2	spi5_clk		I/O	I	up	5mA	✓
GPIO2_C7/SDIO0_D3/SPI5_CSN0	gpio2_c[7]	sdio0_data3	spi5_csn0		I/O	I	up	5mA	✓
GPIO2_D0/SDIO0_CMD	gpio2_d[0]	sdio0_cmd			I/O	I	up	5mA	✓
GPIO2_D1/SDIO0_CLKOUT/TEST_CLKOUT1	gpio2_d[1]	sdio0_clkout	test_clkout1		I/O	I	up	5mA	✓
GPIO2_D2/SDIO0_DET/PCIE_CLKREQN	gpio2_d[2]	sdio0_detect_n	pcie_clkreqn		I/O	I	up	5mA	✓
GPIO2_D3/SDIO0_PWREN	gpio2_d[3]	sdio0_pwren			I/O	I	down	5mA	✓
GPIO2_D4/SDIO0_BKPWR	gpio2_d[4]	sdio0_bkpwr			I/O	I	down	5mA	✓
GPIO3_A0/MAC_TXD2/SPI4_RXD	gpio3_a[0]	mac_txd2	spi4_rxd	trace_data12	I/O	I	down	4mA	✓
GPIO3_A1/MAC_TXD3/SPI4_TXD	gpio3_a[1]	mac_txd3	spi4_txd	trace_data13	I/O	I	down	4mA	✓
GPIO3_A2/MAC_RXD2/SPI4_CLK	gpio3_a[2]	mac_rxd2	spi4_clk	trace_data14	I/O	I	up	4mA	✓
GPIO3_A3/MAC_RXD3/SPI4_CSN0	gpio3_a[3]	mac_rxd3	spi4_csn0	trace_data15	I/O	I	up	4mA	✓
GPIO3_A4/MAC_TXD0/SPI0_RXD	gpio3_a[4]	mac_txd0	spi0_rxd		I/O	I	down	4mA	✓
GPIO3_A5/MAC_TXD1/SPI0_TXD	gpio3_a[5]	mac_txd1	spi0_txd		I/O	I	down	4mA	✓
GPIO3_A6/MAC_RXD0/SPI0_CLK	gpio3_a[6]	mac_rxd0	spi0_clk		I/O	I	up	4mA	✓
GPIO3_A7/MAC_RXD1/SPI0_CSN0	gpio3_a[7]	mac_rxd1	spi0_csn0		I/O	I	up	4mA	✓
GPIO3_B0/MAC_MDC/SPI0_CSN1	gpio3_b[0]	mac_mdc	spi0_csn1		I/O	I	up	4mA	✓
GPIO3_B1/MAC_RXDV	gpio3_b[1]	mac_rxdv			I/O	I	down	4mA	✓

Pin Name	Func 1	Func 2	Func 3	Func 4	Type	Def	PD/PU	Default	INT
GPIO3_B2/MAC_RXER/I2C5_SDA	gpio3_b[2]	mac_rxer	i2c5_sda		I/O	I	up	4mA	✓
GPIO3_B3/MAC_CLK/I2C5_SCL	gpio3_b[3]	mac_clk	i2c5_scl		I/O	I	up	4mA	✓
GPIO3_B4/MAC_TXEN/UART1_RX	gpio3_b[4]	mac_txen	uart1_rx		I/O	I	up	4mA	✓
GPIO3_B5/MAC_MDIO/UART1_TX	gpio3_b[5]	mac_mdio	uart1_tx		I/O	I	up	4mA	✓
GPIO3_B6/MAC_RXCLK/UART3_RX	gpio3_b[6]	mac_rxclk	uart3_rx		I/O	I	up	4mA	✓
GPIO3_B7/MAC_CRS/UART3_TX/CIF_CLKOUTB	gpio3_b[7]	mac_crs	uart3_tx	cif_clkoutb	I/O	I	up	4mA	✓
GPIO3_C0/MAC_COL/UART3_CTSN/SPDIF_TX	gpio3_c[0]	mac_col	uart3_ctsn	spdif_tx	I/O	I	up	4mA	✓
GPIO3_C1/MAC_TXCLK/UART3_RTSN	gpio3_c[1]	mac_txclk	uart3_rtsn		I/O	I	up	4mA	✓
GPIO3_D0/I2S0_SCLK	gpio3_d[0]	i2s0_sclk	trace_data0		I/O	I	down	3mA	✓
GPIO3_D1/I2S0_LRCK_RX	gpio3_d[1]	i2s0_lrck_rx	trace_data1		I/O	I	down	3mA	✓
GPIO3_D2/I2S0_LRCK_TX	gpio3_d[2]	i2s0_lrck_tx	trace_data2		I/O	I	down	3mA	✓
GPIO3_D3/I2S0_SDI0	gpio3_d[3]	i2s0_sdi0	trace_data3		I/O	I	down	3mA	✓
GPIO3_D4/I2S0_SDI1SDO3	gpio3_d[4]	i2s0_sdi1sdo3	trace_data4		I/O	I	down	3mA	✓
GPIO3_D5/I2S0_SDI2SDO2	gpio3_d[5]	i2s0_sdi2sdo2	trace_data5		I/O	I	down	3mA	✓
GPIO3_D6/I2S0_SDI3SDO1	gpio3_d[6]	i2s0_sdi3sdo1	trace_data6		I/O	I	down	3mA	✓
GPIO3_D7/I2S0_SDO0	gpio3_d[7]	i2s0_sdo0	trace_data7		I/O	I	down	3mA	✓
GPIO4_A0/I2S_CLK	gpio4_a[0]	i2s_clk	trace_ctl		I/O	I	down	3mA	✓
GPIO4_A1/I2C1_SDA	gpio4_a[1]	i2c1_sda	trace_clk		I/O	I	up	3mA	✓
GPIO4_A2/I2C1_SCL	gpio4_a[2]	i2c1_scl	trace_data8		I/O	I	up	3mA	✓
GPIO4_A3/I2S1_SCLK	gpio4_a[3]	i2s1_sclk	trace_data9		I/O	I	down	3mA	✓
GPIO4_A4/I2S1_LRCK_RX	gpio4_a[4]	i2s1_lrck_rx	trace_data10		I/O	I	down	3mA	✓
GPIO4_A5/I2S1_LRCK_TX	gpio4_a[5]	i2s1_lrck_tx	trace_data11		I/O	I	down	3mA	✓
GPIO4_A6/I2S1_SDI0	gpio4_a[6]	i2s1_sdi0			I/O	I	down	3mA	✓
GPIO4_A7/I2S1_SDO0	gpio4_a[7]	i2s1_sdo0			I/O	I	down	3mA	✓
GPIO4_B0/SDMMC0_D0/UART2DBG_RX	gpio4_b[0]	sdmmc0_data0	uart2dbg_rx		I/O	I	up	6mA	✓
GPIO4_B1/SDMMC0_D1/UART2DBG_TX	gpio4_b[1]	sdmmc0_data1	uart2dbg_tx	hdcpijtag_trstn	I/O	I	up	6mA	✓

Pin Name	Func 1	Func 2	Func 3	Func 4	Type	Def	PD/PU	Default	INT
GPIO4_B2/SDMMC0_D2/APJTAG_TCK	gpio4_b[2]	sdmmc0_data2	ap_jtag_tck	hdcpjtag_tdi	I/O	I	up	6mA	✓
GPIO4_B3/SDMMC0_D3/APJTAG_TMS	gpio4_b[3]	sdmmc0_data3	ap_jtag_tms	hdcpjtag_tdo	I/O	I	up	6mA	✓
GPIO4_B4/SDMMC0_CLKOUT/MUCJTAG_TCK	gpio4_b[4]	sdmmc0_clkout	mcujtag_tck	hdcpjtag_tck	I/O	I	down	6mA	✓
GPIO4_B5/SDMMC0_CMD/MCUJTAG_TMS	gpio4_b[5]	sdmmc0_cmd	mcujtag_tms	hdcpjtag_tms	I/O	I	up	6mA	✓
GPIO4_C0/I2C3_SDA_HDMI/UART2DBG_RX	gpio4_c[0]	i2c3_sda_hdmi	uart2dbg_rx		I/O	I	up	3mA	✓
GPIO4_C1/I2C3_SCL_HDMI/UART2DBG_TX	gpio4_c[1]	i2c3_scl_hdmi	uart2dbg_tx		I/O	I	up	3mA	✓
GPIO4_C2/PWM0/VOP0_PWM/VOP1_PWM	gpio4_c[2]	pwm0	vop0_pwm	vop1_pwm	I/O	I	down	3mA	✓
GPIO4_C3/UART2DBG_RX/UARTHDCP_RX	gpio4_c[3]	uart2dbg_rx	uarthdcp_rx		I/O	I	up	3mA	✓
GPIO4_C4/UART2DBG_TX/UARTHDCP_TX	gpio4_c[4]	uart2dbg_tx	uarthdcp_tx		I/O	I	up	3mA	✓
GPIO4_C5/SPDIF_TX	gpio4_c[5]	spdif_tx			I/O	I	down	3mA	✓
GPIO4_C6/PWM1	gpio4_c[6]	pwm1			I/O	I	down	3mA	✓
GPIO4_C7/HDMI_CECINOUT/EDP_HOTPLUG	gpio4_c[7]	hdmi_cecinout	edp_hotplug		I/O	I	up	3mA	✓
GPIO4_D0/PCIE_CLKREQN	gpio4_d[0]	pcie_clkreqn			I/O	I	up	3mA	✓
GPIO4_D1/DP_HOTPLUG	gpio4_d[1]	dp_hotplug			I/O	I	down	3mA	✓
GPIO4_D2	gpio4_d[2]				I/O	I	down	3mA	✓
GPIO4_D3	gpio4_d[3]				I/O	I	down	3mA	✓
GPIO4_D4	gpio4_d[4]				I/O	I	down	3mA	✓
GPIO4_D5	gpio4_d[5]				I/O	I	down	3mA	✓
GPIO4_D6	gpio4_d[6]				I/O	I	down	3mA	✓

Notes :

①: Pad types : I = input , O = output , I/O = input/output (bidirectional) ,

AP = Analog Power , AG = Analog Ground

DP = Digital Power , DG = Digital Ground

A = Analog

②: Output Drive strength is configurable, it's the suggested value in this table. Unit is mA , only Digital IO have drive value

③: Reset state: I = input without any pull resistor O = output

④: It is die location. For examples, "Left side" means that all the related IOs are always in left side of die

⑤: Power supply means that all the related IOs are in this IO power domain. If multiple powers are included, they are connected together in one IO power ring

⑥: The pull up/pull down is configurable.

2.9 IO pin name descriptions

This sub-chapter will focus on the detailed function description of every pins based on different interface.

2.8.1 eMMC

Table 2-4eMMC pin description

Interface	Pin Name	Dir.	Description
eMMC	EMMC_PWREN	I/O	eMMC card power control
	EMMC_STRB	I/O	eMMC strobe signal
	EMMC_CLK	O	eMMC clock
	EMMC_CALIO	I/O	CALIO connects to 10k +/- 1% resistor
	EMMC_TP	O	Analog DLL charge pump test point
	EMMC_DATA <i>i</i>	I/O	DATA <i>i</i> (<i>i</i> =0~7), 8bits data lines
	EMMC_CMD	I/O	eMMC CMD line

2.8.2 PCIe

Table 2-5PCIe pin description

Interface	Pin Name	Dir.	Description
PCIe	PCIE_RCLK_100M_N PCIE_RCLK_100M_P	O	100MHz differential reference clock out for PCIe peripheral
	PCIE_TX[<i>i</i>].N PCIE_TX[<i>i</i>].P (<i>i</i> =0~3)	O	PCIe differential data output signals
	PCIE_RX[<i>i</i>].N PCIE_RX[<i>i</i>].P (<i>i</i> =0~3)	I	PCIe differential data input signals
	PCIE_CLKREQN	I	PCIe clock request from PCIe peripheral

2.8.3 USB

Table 2-6USB2 pin description

Interface	Pin Name	Dir.	Description
USB 2.0 (<i>i</i> =0,1)	USB[<i>i</i>].DN	I/O	USB 2.0 data DN
	USB[<i>i</i>].DP	I/O	USB 2.0 data DP
	USB[<i>i</i>].RBIAS	I	Connect 135ohm resistor to ground

Interface	Pin Name	Dir.	Description
USB 3.0 And Type-C (<i>i</i> =0,1)	TYPE_C[<i>i</i>].DN	I/O	USB 2.0 data DN
	TYPE_C[<i>i</i>].DP	I/O	USB 2.0 data DP
	USB[<i>i</i>].RBIAS	I	Connect 135ohm resistor to ground (Shared with USB 2.0 host)
	TYPE_C[<i>i</i>].ID	I	USB 2.0 OTG ID detection
	TYPE_C[<i>i</i>].VBUSDET	I	VBUS BUMP into the PHY for VBUS monitor
	TYPE_C[<i>i</i>].CC2	I/O	Configuration Channel2 pin used for connectiondetect interface configuration and VCONN.

Interface	Pin Name	Dir.	Description
	TYPEC[i]_CC1	I/O	Configuration Channel1 pin used for connectiondetect interface configuration and VCONN.
	TYPEC[i]_TX1P TYPEC[i]_TX1M	O	Lane 0 transmitter serial data - USB Tx or DP Tx. TX+/TX1- USB Type-C receptacle pins (A2/A3)
	TYPEC[i]_TX2P TYPEC[i]_TX2M	O	Lane 3 transmitter serial data - USB Tx or DP Tx. TX2+/TX2- USB Type-C receptacle pins (B2/B3)
	TYPEC[i]_RX1P TYPEC[i]_RX1M	I/O	Lane 1 transmitter/receiver serial data - USB Rx or DP Tx. RX1+/RX1- USB Type-C receptacle pins (B11/B10)
	TYPEC[i]_RX2P TYPEC[i]_RX2M	I/O	Lane 2 transmitter/receiver serial data - USB Rx or DP Tx. RX2+/RX2- USB Type-C receptacle pins (A11/A10)
	TYPEC[i]_RCLKM TYPEC[i]_RCLKP	O	External reference clock. Supports nominal frequencies of 19.2, 20, 24, 27, 54 and 108 MHz. The following external referenceclock sources are supported: • AC coupled differential low swing clock (HCSL levels) • DC single ended clock on ref_p pin. In this mode ref_mshouldbe tied to ground. This mode is for test purposes only. A reference clock must be provided either on these external pinsor the refclock internal SoC-side pin.
	TYPEC[i]_REXT	I	External calibration resistor
	TYPEC[i]_REXT_CC	I	Bump to conect external precision resistors for internalcalibration circuits.
	TYPEC[i]_AUXM/PU_PD TYPEC[i]_AUXP/PD_PU	I/O	AUX pull-up/pull-down polarity reversal pins. For normal connectororientation, there is a weak pull-down on aux_p wires and aweak pull-up on aux_m wire. These pins are used to reverse thisfor the flipped connector case.
	TYPEC[i]_AUXM TYPEC[i]_AUXP	I/O	AUX differential Tx/Rx serial data

2.8.4 eDP

Table 2-7eDP pin description

Interface	Pin Name	Dir.	Description
eDP	EDP_TX/P(i=0~3)	O	eDP data lane positive output
	EDP_TX/N(i=0~3)	O	eDP data lane negative output
	EDP_DC_TP	O	eDP PHY DC test point
	EDP_AUXP	I/O	eDP CH-AUX positive differential output
	EDP_AUXN	I/O	eDP CH-AUX negative differential output
	EDP_REXT	I	eDP reference resistor connection. Recommend to use a 6.04KΩ resistor
	EDP_CLK24M_IN	I	24MHz input reference clock
	EDP_HOTPLUG	I	eDP external hot plug signal

2.8.5 HDMI

Table 2-8HDMI pin description

Interface	Pin Name	Dir.	Description
HDMI	HDMI_TXiN($i=0\sim2$)	O	HDMI negative TMDS differential line driver data output
	HDMI_XiP($i=0\sim2$)	O	HDMI positive TMDS differential line driver data output
	HDMI_TCN	O	HDMI negative TMDS differential line driver clock output
	HDMI_TCP	O	HDMI positive TMDS differential line driver clock output
	HDMI_REXT	I/O	HDMI reference resistor connection
	HDMI_HPD	I/O	HDMI hot plug detect signal
	I2C3_SDA_HDMI	I/O	I2C data line for HDMI
	I2C3_SCL_HDMI	I/O	I2C clock line for HDMI
	HDMI_CECINOUT	I/O	HDMI CEC signal

2.8.6 MIPI

Table 2-9MIPI pin description

Interface	Pin Name	Dir.	Description
MIPI_DSI	MIPI_TX0_DiN($i=0\sim3$)	I/O	MIPI DSI negative differential data line transceiver output
	MIPI_TX0_DiP($i=0\sim3$)	I/O	MIPI DSI positive differential data line transceiver output
	MIPI_TX0_CLKP	I/O	MIPI DSI positive differential clock line transceiver output
	MIPI_TX0_CLKN	I/O	MIPI DSI negative differential clock line transceiver output
	MIPI_TX0_REXT	I/O	MIPI DSI external resistor connection. Recommend to use a 4.02 K Ω E96 resistor.

Interface	Pin Name	Dir.	Description
MIPI_CSI	MIPI_RX0_DiN($i=0\sim3$)	I/O	MIPI CSI negative differential data line transceiver output
	MIPI_RX0_DiP($i=0\sim3$)	I/O	MIPI CSI positive differential data line transceiver output
	MIPI_RX0_CLKP	I/O	MIPI CSI positive differential clock line transceiver output
	MIPI_RX0_CLKN	I/O	MIPI CSI negative differential clock line transceiver output
	MIPI_RX0_REXT	I/O	MIPI CSI external resistor connection. Recommend to use a 4.02 K Ω E96 resistor.

Interface	Pin Name	Dir.	Description
MIPI_CSI/DSI	MIPI_TX1/RX1_DiN($i=0\sim3$)	I/O	MIPI CSI negative differential data line transceiver output
	MIPI_TX1/RX1_DiP($i=0\sim3$)	I/O	MIPI CSI positive differential data line transceiver output
	MIPI_TX1/RX1_CLKP	I/O	MIPI CSI positive differential clock line transceiver output
	MIPI_TX1/RX1_CLKN	I/O	MIPI CSI negative differential clock line transceiver output
	MIPI_TX1/RX1_REXT	I/O	MIPI CSI external resistor connection. Recommend to use a 4.02 K Ω E96 resistor.

2.8.7 ISP

Table 2-10ISP pin description

Interface	Pin Name	Dir.	Description
ISP	ISP_SHUTTER_ENi($i=0\sim1$)	O	Hold signal for shutter open
	ISP_FLASHTRIGOUTi($i=0\sim1$)	O	Hold signal for flash light
	ISP_PRELIGHT_TRIGi($i=0\sim1$)	O	Hold signal for prelight
	ISP_SHUTTER_TRIGi($i=0\sim1$)	I	External shutter trigger pulse
	ISP_FLASHTRIGINi($i=0\sim1$)	I	External flash trigger pulse

2.8.8 EFUSE

Table 2-11EFUSE pin description

Interface	Pin Name	Dir.	Description
eFuse	EFUSE	N/A	eFuse program and sense power

2.8.9 SAR-ADC

Table 2-12SAR-ADC pin description

Interface	Pin Name	Dir.	Description
SAR-ADC	ADC_IN[i](i=0~5)	N/A	SAR-ADC input signal for 3 channel

2.8.10 TSADC

Table 2-13TSADC pin description

Interface	Pin Name	Dir.	Description
TSADC	TSADC_INT	O	TSADC interrupt signal for over temperature

2.8.11 GMAC

Table 2-14GMAC pin description

Interface	Pin Name	Dir.	Description
GMAC	MAC_CLK	I/O	RMII REC_CLK output or GMAC external clock input
	MAC_TXCLK	O	RGMIITX clock output
	MAC_RXCLK	I	RGMIIRX clock input
	MAC_MDC	O	GMAC management interface clock
	MAC_MDIO	I/O	GMAC management interface data
	MAC_TXDi(i=0~3)	O	GMAC TX data
	MAC_RXDi(i=0~3)	I	GMAC RX data
	MAC_TXEN	O	GMAC TX data enable
	MAC_RXDV	I	GMAC RX data valid signal
	MAC_RXER	I	GMAC RX error signal
	MAC_COL	I	PHY Collision signal
	MAC_CRS	I	PHY CRS signal

2.8.12 UART

Table 2-15UART pin description

Interface	Pin Name	Dir.	Description
UART[i] i=0,3	UART[i]_RX	I	UARTsearial data input
	UART[i]_TX	O	UARTsearial data output
	UART[i]_CTSN	I	UART clear to send
	UART[i]_RTSN	O	UART request to send

Interface	Pin Name	Dir.	Description
UART[i] i=1,2,4	UART[i]_RX	I	UARTsearial data input
	UART[i]_TX	O	UARTsearial data output

Note: UART2 is to be debug port by default.

2.8.13 I2C

Table 2-16I2C pin description

Interface	Pin Name	Dir.	Description
I2C[i] i=0~8	I2C[i]_SDA	I	I2C data line
	I2C[i]_SCL	O	I2C serial clock line

2.8.14 PWM

Table 2-17 PWM pin description

Interface	Pin Name	Dir.	Description
PWM	PWM0	I/O	Pulse Width Modulation output
	PWM1	I/O	Pulse Width Modulation output
	PWM2	I/O	Pulse Width Modulation output
	PWM3_IR	I/O	Pulse Width Modulation output, special design for IR receiver
	VOPO_PWM	I/O	CABC PWM from VOPO
	VOP1_PWM	I/O	CABC PWM from VOP1

2.8.15 CIF

Table 2-18 CIF pin description

Interface	Pin Name	Dir.	Description
Camera IF	CIF_CLKIN	I	Camera interface input pixel clock
	CIF_CLKOUT	O	Camera interface output work clock
	CIF_CLKOUTB	O	Camera interface output work clock
	CIF_VSYNC	I	Camera interface vertical sync signal
	CIF_HREF	I	Camera interface horizontal sync signal
	CIF_D[i](i=0~7)	I	Camera interface input pixel data

2.8.16 SPI

Table 2-19 SPI pin description

Interface	Pin Name	Dir.	Description
SPI0	SPI0_CLK	I/O	SPI serial clock
	SPI0_CSN0	I/O	SPI first chip select signal, low active
	SPI0_CSN1	I/O	SPI second chip select signal, low active
	SPI0_TXD	O	SPI serial data output
	SPI0_RXD	I	SPI serial data input

Interface	Pin Name	Dir.	Description
SPI[i] i=1~5	SPI[i]_CLK	I/O	SPI serial clock
	SPI[i]_CSN0	I/O	SPI first chip select signal, low active
	SPI[i]_TXD	O	SPI serial data output
	SPI[i]_RXD	I	SPI serial data input

2.8.17 SPDIF

Table 2-20 SPDIF pin description

Interface	Pin Name	Dir.	Description
S/PDIF	SPDIF_TX	O	S/PDIF biphasic data output

2.8.18 I2S

Table 2-21I2S pin description

Interface	Pin Name	Dir.	Description
I2S	I2S_CLK	O	I2S/PCM clock source, shared by I2S0 and I2S1

Interface	Pin Name	Dir.	Description
I2S0/PCM0 8 channels	I2S0_SCLK	I/O	I2S/PCM serial clock
	I2S0_LRCK_RX	I/O	I2S/PCM left & right channel signal for receiving serial data, synchronous left & right channel in I2S mode and the beginning of a group of left & right channels in PCM mode
	I2S0_LRCK_TX	I/O	I2S/PCM left & right channel signal for transmitting serial data, synchronous left & right channel in I2S mode and the beginning of a group of left & right channels in PCM mode
	I2S0_SDI0	I	I2S/PCM serial data input[0]
	I2S0_SDI1SDO3	I	I2S/PCM serial data input[1] or output [3]
	I2S0_SDI2SDO2	I	I2S/PCM serial data input [2] or output [2]
	I2S0_SDI3SDO1	I	I2S/PCM serial data input [3] or output [1]
	I2S0_SDO0	I	I2S/PCM serial data output [0]

Interface	Pin Name	Dir.	Description
I2S1/PCM1 2 channels	I2S1_SCLK	I/O	I2S/PCM serial clock
	I2S1_LRCK_RX	I/O	I2S/PCM left & right channel signal for receiving serial data, synchronous left & right channel in I2S mode and the beginning of a group of left & right channels in PCM mode
	I2S1_LRCK_TX	I/O	I2S/PCM left & right channel signal for transmitting serial data, synchronous left & right channel in I2S mode and the beginning of a group of left & right channels in PCM mode
	I2S1_SDI0	I	I2S/PCM serial data input [0]
	I2S1_SDO0	I	I2S/PCM serial data output [0]

2.8.19 DDR Controller

Table 2-22DDRC pin description

Interface	Pin Name	Dir.	Description
DDR[i] Controller (i=0,1)	DDR[i]_ATB[j] (j=0,1)	O	Analog test bus signals
	DDR[i]_CLK[j]N DDR[i]_CLK[j]P (j=0~1)	O	Differential clock signal to the memory device
	DDR[i]_CKE[j] (j=0,1)	O	Active-high clock enable signal to the memory device for two chip select.
	DDR[i]_CSN[j] (j=0~3)	O	Active-low chip select signal to the memory device. There are two chip select.
	DDR[i]_RASN	O	Active-low row address strobe to the memory device.
	DDR[i]_CASN	O	Active-low column address strobe to the memory device.
	DDR[i]_WEN	O	Active-low write enable strobe to the memory device.
	DDR[i]_BA[2:0]	O	Bank address signal to the memory device.
	DDR[i]_A[15:0]	O	Address signal to the memory device.
	DDR[i]_DQ[31:0]	I/O	Bidirectional data line to the memory device.
	DDR[i]_DQS[j]N[j=0~3]	I/O	Differential data strobes to/from the memories. For writes, the pad drives these signals. For reads, the memory drives these signals.
	DDR[i]_DQS[j]P[j=0~3]	I/O	

Interface	Pin Name	Dir.	Description
	DDR[i]_DM[3:0]	O	Active-low data mask signal to the memory device.
	DDR[i]_ODT[j](j=0,1)	O	On-Die Termination output signal for two chip select.
	DDR[i]_RESETN	O	DDR reset signal to the memory device
	DDR0_PLL_TESTOUT_P DDR0_PLL_TESTOUT_N	O	DDR PLL test point
	DDR[i]_PZQ	I/O	ZQ calibration pad which connects 240ohm $\pm$ 1% resistor

2.8.20 SDIO

Table 2-23SDIO pin description

Interface	Pin Name	Dir.	Description
SDIO Host Controller	SDIO0_CLKOUT	O	SDIO card clock.
	SDIO0_CMD	I/O	SDIO card command output and reponse input.
	SDIO0_D[0:3]	I/O	SDIOcard data input and output.
	SDIO0_DET N	I	SDIOcard detect signal, a 0 represents presence of card.
	SDIO0_WRPT	I	SDIOcard write protect signal, a 1 represents write is protected.
	SDIO0_PWREN	O	SDIOcard power-enable control signal
	SDIO0_INTN	O	SDIOcard interrupt indication
	SDIO0_BKPWR	O	the back-end power supply for embedded device

2.8.21 SDMMC

Table 2-24SDMMC pin description

Interface	Pin Name	Dir.	Description
SD/MMC Host Controller	SDMMC0_CLKOUT	O	SDMMC card clock
	SDMMC0_CMD	I/O	SDMMCCard command output and reponse input
	SDMMC0_D[0:3]	I/O	SDMMCCard data input and output
	SDMMC0_WRPRT	I	SDMMC card protect
	SDMMC0_DET	I	SDMMCCard detect signal, a 0 represents presence of card
	SDMMC0_VDDPST	O	Pin out to external capacitor

2.8.22 JTAG

Table 2-25JTAG pin description

Interface	Pin Name	Dir.	Description
AP JTAG	APJTAG_TCK	I	APJTAG interface clock input/SWD interface clock input
	APJTAG_TMS	I/O	APJTAG interface TMS input/SWD interface data out

Note: AP means CPU core in RK3399 including Cortex A72 and Cortex A53.

Interface	Pin Name	Dir.	Description
MCU JTAG	MCUJTAG_TCK	I	MCUJTAG interface clock input/SWD interface clock input
	MCUJTAG_TMS	I/O	MCUJTAG interface TMS input/SWD interface data out

Note: MCU means built-in micro-controller in RK3399 core domain.

Interface	Pin Name	Dir.	Description
PMCU	PMCU_JTAG_TCK	I	PMU MCU JTAG interface clock input/SWD interface clock input
JTAG	PMCU_JTAG_TMS	I/O	PMU MCU JTAG interface TMS input/SWD interface data out

Note: PMCU means built-in micro-controller in RK3399 PMU domain.

2.8.23 MISC

Table 2-26 MISC pin description

Interface	Pin Name	Dir.	Description
Misc	XIN_OSC	I	Clock input of 24MHz crystal
	XOUT_OSC	O	Clock output of 24MHz crystal
	CLK32K	I	Clock input of 32.768KHz
	NPOR	I	Chip hardware reset
	AP_PWROFF	O	System power off control port (PMIC_SLEEP)
	WIFI_26MHZ	O	26MHz clock out for WIFI chip

Chapter 3 Electrical Specification

3.1 Absolute Maximum Ratings

Table 3-1 Absolute maximum ratings

Parameters	Related Power Group	Max	Unit
DC supply voltage for Internal digital logic	BIGCPU_VDD, LITCPU_VDD, LOGIC_VDD, CENTERLOGIC_VDD	1.3	V
DC supply voltage for DDR IO	DDR_VDD	1.65	V
Highest Storage Temperature	Tstg	125	°C
Lowest Storage Temperature	Tstg	-40	°C
Max Junction Temperature	Tj	125	°C
ESD (HBM)		>2000	V

Absolute maximum ratings specify the values beyond which the device may be damaged permanently. Long-term exposure to absolute maximum ratings conditions may affect device reliability.

3.2 Recommended Operating Conditions

The below table describes the recommended operating condition for every clock domain.

Table 3-2 Recommended operating conditions

Parameters	Symbol	Min	Typ	Max	Units
Supply voltage for Cortex A72 CPU	BIGCPU_VDD	0.80	0.90	1.25	V
Supply voltage for Cortex A53 CPU	LITCPU_VDD	0.80	0.90	1.20	V
Max frequency of Cortex A72 CPU	RK3399 0°C~80°C			1.8	GHz
Max frequency of Cortex A53 CPU				1.4	GHz
Max frequency of Cortex A72 CPU	RK3399K 0°C~80°C			2.0	GHz
Max frequency of Cortex A53 CPU				1.6	GHz
Max frequency of Cortex A72 CPU	RK3399K -20°C~0°C or 80~85°C			1.8	GHz
Max frequency of Cortex A53 CPU				1.4	GHz
Supply voltage for GPU	GPU_VDD	0.80	0.90	1.20	V
Max frequency of GPU	RK3399			800	MHz
Max frequency of GPU	RK3399K 0°C~80°C			800	MHz
Max frequency of GPU	RK3399K -20°C~0°C or 80~85°C			600	MHz
Internal digital logic Power	CENTERLOGIC_VDD LOGIC_VDD	0.8	0.9	1.0	V
PMU digital logic power (0.9V)	PMU_VDD_0V9	0.81	0.9	0.99	V
PMU digital logic power (1.8V)	PMU_VDD_1V8	1.62	1.8	1.98	V
EMMC power	EMMC_VDD_1V8	1.62	1.8	1.98	V
Supply voltage for digital GPIO@1.8V mode	PMUIO1_VDD_1V8	1.62	1.8	1.98	V

Parameters	Symbol	Min	Typ	Max	Units
	PMUIO2_VDDPST	1.71	1.8	1.89	
	PMUIO2_VDD	1.71	1.8	1.89	
	APIO2_VDDPST	1.71	1.8	1.89	
	APIO2_VDD	1.71	1.8	1.89	
	APIO3_VDD_1V8	1.62	1.8	1.98	
	APIO4_VDDPST	1.71	1.8	1.89	
	APIO4_VDD	1.71	1.8	1.89	
	APIO5_VDDPST	1.71	1.8	1.89	
	APIO5_VDD	1.71	1.8	1.89	
	SDMMC0_VDD	1.71	1.8	1.89	
Supply voltage for digital GPIO@3.0V mode	PMUIO2_VDDPST	1.425	1.5	1.575	V
	PMUIO2_VDD	2.85	3.0	3.15	
	APIO2_VDDPST	1.425	1.5	1.575	
	APIO2_VDD	2.85	3.0	3.15	
	APIO4_VDDPST	1.425	1.5	1.575	
	APIO4_VDD	2.85	3.0	3.15	
	APIO5_VDDPST	1.425	1.5	1.575	
	APIO5_VDD	2.85	3.0	3.15	
	SDMMC0_VDD	2.85	3.0	3.15	
Supply voltage for digital GPIO@3.3V mode	APIO1_VDDPST	1.71	1.8	1.89	V
	APIO1_VDD	3.135	3.3	3.465	
Supply voltage for DDR0/ DDR1	DDRPLL_AVDD_0V9	0.81	0.9	0.99	V
	DDR_VDD@DDR3	1.425	1.5	1.575	
	DDR_VDD@DDR3L	1.28	1.35	1.42	
	DDR_VDD@LPDDR3	1.14	1.2	1.3	
	DDR_VDD@LPDDR4	1.06	1.1	1.17	
	DDR_CLK_VDD@DDR3	1.425	1.5	1.575	
	DDR_CLK_VDD@DDR3L	1.28	1.35	1.42	
	DDR_CLK_VDD@LPDDR3	1.14	1.2	1.3	
	DDR_CLK_VDD@LPDDR4	1.06	1.1	1.17	
Supply voltage for SAR-ADC	ADC_AVDD	1.62	1.8	1.98	V
Supply voltage for EFUSE	EFUSE	1.62	1.8	1.98	V
Supply voltage for PLL	PLL_AVDD_0V9	0.81	0.9	0.99	V
	PLL_AVDD_1V8	1.62	1.8	1.98	
Supply voltage for EDP	EDP_AVDD_0V9	0.81	0.9	0.99	V
	EDP_AVDD_1V8	1.62	1.8	1.98	
Supply voltage for EMMC	EMMC_COREDLL_0V9	0.81	0.9	0.99	V
	EMMC_VDD_1V8	1.62	1.8	1.98	
Supply voltage for HDMI	HDMI_AVDD_0V9	0.81	0.9	0.99	V
	HDMI_AVDD_1V8	1.62	1.8	1.98	
Supply voltage for MIPI	MIPI_TX0_AVDD_1V8	1.62	1.8	1.98	V
	MIPI_TX1/RX1_AVDD_1V8				
	MIPI_RX0_AVDD_1V8				
Supply voltage for PCIE	PCIE_AVDD_0V9	0.81	0.9	0.99	V
	PCIE_AVDD_1V8	1.62	1.8	1.98	

Parameters	Symbol	Min	Typ	Max	Units
Supply voltage for TYPEC	TYPEC0_AVDD_0V9	0.81	0.9	0.99	V
	TYPEC0_AVDD_1V8	1.62	1.8	1.98	
	TYPEC0_AVDD_3V3	2.97	3.3	3.63	
	TYPEC1_AVDD_0V9	0.81	0.9	0.99	
	TYPEC1_AVDD_1V8	1.62	1.8	1.98	
	TYPEC1_AVDD_3V3	2.97	3.3	3.63	
Supply voltage for USIC	USIC_AVDD_0V9	0.81	0.9	0.99	V
	USIC_AVDD_1V2	1.08	1.2	1.32	
Supply voltage for USB	USB_AVDD_0V9	0.81	0.9	0.99	V
	USB_AVDD_1V8	1.62	1.8	1.98	
	USB_AVDD_3V3	2.97	3.3	3.63	
PLL input clock frequency		N/A	24	N/A	MHz
Ambient Operating Temperature for RK3399	Ta	0	25	80	℃
Ambient Operating Temperature for RK3399K	Ta	-20	25	85	℃

Notes:

- 1) Symbol name is same as the pin name in the IO descriptions
- 2) with the reference software setup, the reference software will limit the chipset temperature about 85℃

3.3 DC Characteristics

Table 3-3DC Characteristics

Parameters		Symbol	Min	Typ	Max	Units
Digital GPIO @3.3V	Input Low Voltage	Vil	-0.3	N/A	0.8	V
	Input High Voltage	Vih	2.0	N/A	3.465	V
	Output Low Voltage	Vol	N/A	N/A	0.4	V
	Output High Voltage	Voh	2.4	N/A	N/A	V
	Pull up resistor	RPU	26	46	71	kΩ
	Pull down resistor	RPD	27	48	102	kΩ
Digital GPIO @1.8V	Input Low Voltage	Vil	-0.3	N/A	0.63	V
	Input High Voltage	Vih	1.17	N/A	1.98	V
	Output Low Voltage	Vol	N/A	N/A	0.45	V
	Output High Voltage	Voh	1.35	N/A	N/A	V
	Pull up resistor	RPU	33	58	88	kΩ
	Pull down resistor	RPD	34	60	93	kΩ
Digital GPIO @3.0V	Input Low Voltage	Vil	-0.3	N/A	0.71	V
	Input High Voltage	Vih	1.875	N/A	3.15	V
	Output Low Voltage	Vol	N/A	N/A	0.375	V
	Output High Voltage	Voh	2.25	N/A	N/A	V
	Pullup Resistor	RPU	33	59	89	kΩ
	Pulldown Resistor	RPD	34	61	95	kΩ
DDR IO	I/O supply voltage VIOS	DDR3	1.425	1.5	1.575	V
		DDR3L	1.28	1.35	1.42	V
		LPDDR3	1.14	1.2	1.3	V
		LPDDR4	1.06	1.1	1.17	V
	I/O output voltage	DDR3	0.49	0.50	0.51	VIOS

Parameters		Symbol	Min	Typ	Max	Units
	VIOT	DDR3L	0.49	0.50	0.51	VIOS
		LPDDR3		1		VIOS
		LPDDR4		0		
MIPI_DSI IO	HS TX static Common-mode voltage	VCMTX	150	200	250	mV
	VCMTX mismatch when output is Differential-1 or Differential-0	Δ VCMTX(1,0)	N/A	N/A	5	mV
	HS transmit differential voltage	VOD	140	200	270	mV
	VOD mismatch when output is Differential-1 or Differential-0	Δ VOD	N/A	N/A	14	mV
	HS output high voltage	VOHHS	N/A	N/A	360	mV
	Single ended output impedance	ZOS	40	50	62.5	Ω
	Single ended output impedance mismatch	Δ ZOS	N/A	N/A	10	%
HDMI	Single-ended standby voltage	Voff	avddtmds $\pm$ 10			mV
	Single-ended output swing voltage RT=50 Ω	Vswing	400	N/A	600	mV
		Vswing_data	400	N/A	600	mV
		Vswing_clock	200	N/A	600	mV
	Single-ended output high voltage	Vh	avddtmds $\pm$ 10			mV
			avddtmds-200	N/A	avddtmds+10	mV
		Vh_data	avddtmds-400	N/A	avddtmds+10	mV
		Vh_clock	avddtmds-400	N/A	avddtmds+10	mV
	Single-ended output low voltage	VI	avddtmds-600	N/A	avddtmds-400	mV
			avddtmds-700	N/A	avddtmds-400	mV
		VI_data	avddtmds-1000	N/A	avddtmds-400	mV
		VI_clock	avddtmds-1000	N/A	avddtmds-200	mV
	Differential source termination load	Rterm	50	N/A	200	Ω

3.4 Electrical Characteristics for General IO

Table 3-4 Electrical Characteristics for Digital General IO

Parameters		Symbol	Test condition	Min	Typ	Max	Units
Digital	Input leakage current	Ii	Vin = 3.3V or 0V	N/A	N/A	10	μ A
GPIO @3.3V	Tri-state output leakage current	Ioz	Vout = 3.3V or 0V	N/A	N/A	10	μ A

Parameters		Symbol	Test condition	Min	Typ	Max	Units
	High level output current	Oih	25°C	6	N/A	63.8	mA
	Low level output current	Oil	25°C	4	N/A	38.5	mA
Digital GPIO @1.8V	Input leakage current	Ii	Vin = 1.8V or 0V	N/A	N/A	10	uA
	Tri-state output leakage current	Ioz	Vout = 1.8V or 0V	N/A	N/A	10	uA
	High level output current	Oih	25°C	3.7	N/A	24.6	mA
	Low level output current	Oil	25°C	4.8	N/A	26.1	mA
Digital GPIO @3.0V	Input leakage current	Ii	Vin = 3.0V or 0V	N/A	N/A	10	uA
	Tri-state output leakage current	Ioz	Vout = 3.0V or 0V	N/A	N/A	10	uA
	Pull up resistor	RPU					
	Pull down resistor	RPD					
	High level output current	Oih	25°C	5.0	N/A	27.9	mA
	Low level output current	Oil	25°C	3.1	N/A	20.1	mA

3.5 Electrical Characteristics for PLL

Table 3-5 Electrical Characteristics for PLL

Parameters	Symbol	Test condition	Min	Typ	Max	Units
Output frequency range	Fout		1	N/A	3200	MHz
Lock time	Tlt		N/A	250	500	Input clock cycles
Power consumption (normal mode)	N/A	FVCO=1GHz	N/A	3	N/A	mW
Period jitter (random)	N/A	VCO=3200MHz	N/A	NA	0.11	Ps(RMS)
Junction temperature	N/A		N/A	25	125	°C

3.6 Electrical Characteristics for SAR-ADC

Table 3-6 Electrical Characteristics for SAR-ADC

Parameters	Symbol	Test condition	Min	Typ	Max	Units
ADC resolution			N/A	10	N/A	bits
Clock frequency	fCLK		N/A	N/A	13	MHz
Clock period	tCLK		75	N/A	N/A	ns
Conversion time	Fs		13	N/A	N/A	tCLK
Differential Non Linearity	DNL		N/A	±1	N/A	LSB
Integral Non Linearity	INL		N/A	±2	N/A	LSB
Analog Supply Current	IAVDD		N/A	450	N/A	uA
Digital Supply Current	IVDD		N/A	50	N/A	uA
Power Down Current from AVDD			NA	1	NA	uA
Power Down Current from DVDD			N/A	1	N/A	uA
Setup up time	ts		N/A	0.5	N/A	tCLK

3.7 Electrical Characteristics for TSADC

Table 3-7 Electrical Characteristics for TSADC

Parameters	Symbol	Test condition	Min	Typ	Max	Units
ADC resolution			N/A	10	N/A	bits
TSADC Accuracy	Fs		N/A	N/A	5	°C
Active power			N/A	0.17	N/A	mW
Clock Frequency	Fclk		N/A	NA	800	KHz
Power Down Current from DVDD			N/A	1	N/A	uA

3.8 Electrical Characteristics for Type-C PHY

Table 3-8 Electrical Characteristics for Type-C PHY

Parameters	Symbol	Test condition	Min	Typ	Max	Units
Transmitter						
High input level	VIH		NA	1.0	NA	V

3.9 Electrical Characteristics for USB2.0 PHY

Table 3-9 Electrical Characteristics for USB2.0 PHY

Parameters	Symbol	Test condition	Min	Typ	Max	Units
Transmitter						
High input level	VIH		NA	1.0	NA	V
Low input level	VIL		NA	0	NA	V
Output resistance	ROUT	Classic mode (Vout = 0 or 3.3V)	40.5	45	49.5	ohms
		HS mode (Vout = 0 to 800mV)	40.5	45	49.5	ohms
Output Capacitance	COUT	seen from D+ or D-			3	pF
Output Common Mode Voltage	VM	Classic (LS/FS) mode	1.45	1.65	1.85	V
		HS mode	0.175	0.2	0.225	V
Differential output signal high	VOH	Classic (LS/FS); Io=0mA	2.97	3.3	3.63	V
		Classic (LS/FS); Io=6mA	2.2	0.3	NA	V
		HS mode; Io=0mA	360	400	440	mV
Differential output signal low	VOL	Classic (LS/FS); Io=0mA	-0.33	0	0.33	V
		Classic (LS/FS); Io=6mA	NA	0.3	0.8	V
		HS mode; Io=0mA	-40	0	40	mV
Receiver						
Receiver sensitivity	RSENS	Classic mode		+ -250		mV

Parameters	Symbol	Test condition	Min	Typ	Max	Units
		HS mode		+ -25		mV
Receiver common mode	RCM	Classic mode	0.8	1.65	2.5	V
		HS mode (differential and squelch comparator)	0.1	0.2	0.3	V
		HS mode (disconnect comparator)	0.5	0.6	0.7	V
Input capacitance (seen at D+ or D-)			NA	NA	3	pF
Squelch threshold			100	112	150	mV
Disconnect threshold			570	590	625	mV
High output level	VOH		NA	3.3	NA	V
Low output level	VOL		NA	0	NA	V

3.10 Electrical Characteristics for DDR IO

Table 3-10 Electrical Characteristics for DDR IO

Parameters		Symbol	Test condition	Min	Typ	Max	Units
DDR IO @DDR3 mode	Input leakage current		@ 1.5V	-2	N/A	2	uA
DDR IO @DDR3L mode	Input leakage current		@ 1.35V	-2	N/A	2	uA
DDR IO @LPDDR3 mode	Input leakage current		@ 1.2V	-2	N/A	2	uA
DDR IO @LPDDR4 mode	Input leakage current		@ 1.1V	-2	N/A	2	uA

3.11 Electrical Characteristics for eFuse

Table 3-11 Electrical Characteristics for eFuse

	Parameters	Symbol	Test condition	Min	Typ	Max	Units
Active mode	VDD current in Read mode	Iread_vdd	nomal read	N/A	9	N/A	mA
	VDD current in PGM mode	Ipgm_vdd	STROBE high	N/A	17	N/A	mA
	VQPS current in PGM mode	Ipgm_vqps	STROBE high	N/A	0.2	N/A	uA
standby mode	VDD current in standby mode	Istandby_vdd	Standby	N/A	10	N/A	uA

3.12 Electrical Characteristics for HDMI

Table 3-12 Electrical Characteristics for HDMI

Parameters	Symbol	Test condition	Min	Typ	Max	Units
Differential output signal rise time	tR	20~80% RL=50Ω	75	N/A	0.4UI	ps

Parameters	Symbol	Test condition	Min	Typ	Max	Units
Differential output signal fall time	tR_DATA	20~80% RL=50Ω	42.5	N/A	N/A	ps
	tR_CLOCK	20~80% RL=50Ω	75	N/A	N/A	ps
	tF	20~80% RL=50Ω	75	N/A	N/A	ps
Differential output signal fall time	tF_DATA	20~80% RL=50Ω	42.5	N/A	N/A	ps
	tF_CLOCK	20~80% RL=50Ω	75	N/A	N/A	ps

3.13 Electrical Characteristics for MIPI PHY

Table 3-13 Electrical Characteristics for MIPI PHY

Parameters	Symbol	Test condition	Min	Typ	Max	Units
HS Transmitter AC specifications (MIPI mode)						
Common-mode variations above 450 MHz	ΔVCMTX(HF)		N/A	N/A	15	mVRMS
Common-mode variations between 50MHz – 450MHz	ΔVCMTX(LF)		N/A	N/A	25	mVPEAK
20%-80% rise time and fall time	TR and TF		100	N/A	N/A	ps
HS Receiver AC specifications (MIPI mode)						
Common-mode interference beyond 450 MHz	ΔVCMRX(HF)		N/A	N/A	200	mV
Common-mode interference	ΔVCMRX(LF)		-50	NA	50	mV
Common-mode termination	CCM		N/A	N/A	60	pF
LP receiver AC specifications(MIPI mode)						
Input pulse rejection	eSPIKE		N/A	N/A	300	V.ps
Minimum pulse width response	TMIN-RX		20	N/A	N/A	ns
Peak interference amplitude	VINT		N/A	N/A	400	mV
Interference frequency	fINT		450	N/A	N/A	MHz
LP Transmitter AC Specifications(MIPI mode)						
15%-85% rise time and fall time	TRLP/TFLP		N/A	N/A	25	ns
30%-85% rise time and fall time	TREOT		N/A	N/A	35	ns
Slew rate	δV/δtSR		N/A	N/A	150	mV/ns
Load capacitance	CLOAD		0	N/A	70	pF

3.14 Electrical Characteristics for eMMC PHY

Table 3-14 Electrical Characteristics for eMMC PHY

Parameters	Symbol	Test condition	Min	Typ	Max	Units
Input leakage current			N/A	12	N/A	pA
Tri-state output leakage current			N/A	10	N/A	pA

3.15 Electrical Characteristics for PCIe PHY

Table 3-15 Electrical Characteristics for PCIe PHY

Parameters	Symbol	Condition	Min	Typ	Max	Units
Transmitter						
Unit Interval	UI	2.5GT/s	399.88	N/A	400.12	ps
Differential p-pTx voltage swing	V _{TX-DIFF-PP}	2.5GT/s	0.8	N/A	1.2	V
Low powerdifferential p-p Txvoltage swing	V _{TX-DIFF-PP-LOW}	2.5GT/s	0.4	N/A	1.2	V
Tx de-emphasislevel ratio	V _{TX-DE-RATIO-3.5dB}	2.5GT/s	3.0	N/A	4.0	dB
Transmitter Eyeincluding all jittersources	T _{TX-EYE}	2.5GT/s	0.75	N/A	N/A	UI
Maximum timebetween the jittermedian and maxdeviation fromthe median	T _{TX-EYE-MEDIAN-to-MAX-JITTER}	2.5GT/s	N/A	N/A	0.125	UI
Transmitter riseand fall time	T _{TX-RISE-FALL}	2.5GT/s	0.125	N/A	N/A	UI
Tx package plusSi differentialreturn loss	RL _{TX-DIFF}	2.5GT/s	10	N/A	N/A	dB
Tx package plusSi commonmode return loss	RL _{TX-CM}	2.5GT/s	6	N/A	N/A	dB
Tx AC commonmode voltage	V _{TX-CM-AC-P}	2.5GT/s	20	N/A	N/A	mV
Transmittershort-circuitcurrent limit	I _{TX-SHORT}	2.5GT/s	N/A	N/A	90	mA
Transmitter DCcommon-modevoltage	V _{TX-DC-CM}	2.5GT/s	0	N/A	3.6	V
Absolute Delta ofDC CommonMode Voltageduring L0 and Electrical Idle.	V _{TX-CM-DC-ACTIVEIDLE-DELTA}	2.5GT/s	0	N/A	100	mV
Electrical IdleDifferential PeakOutput Voltage	V _{TX-IDLE-DIFF-AC-p}	2.5GT/s	0	N/A	20	mV
The amount ofvoltage changeallowed duringReceiverDetection	V _{TX-RCV-DETECT}	2.5GT/s	N/A	N/A	600	mV
Minimum timespent inElectrical Idle	T _{TX-IDLE-MIN}	2.5GT/s	20	N/A	N/A	ns
Maximum time totransition to avalid ElectricalIdle after sendingan EIOS	T _{TX-IDLE-SET-TOIDLE}	2.5GT/s	N/A	N/A	8	ns
Maximum time totransition to validdiff signalingafter leavingElectrical Idle	T _{TX-IDLE-TO-DIFFDATA}	2.5GT/s	N/A	N/A	8	ns
Crosslinkrandom timeout	T _{CROSSLINK}	2.5GT/s	N/A	N/A	1.0	ms
AC CouplingCapacitor	C _{TX}	2.5GT/s	75	N/A	200	nF
Receiver						
Unit Interval	UI	2.5GT/s	399.88	N/A	400.12	ps

Parameters	Symbol	Condition	Min	Typ	Max	Units
Differential Rx peak-peak voltage for common Refclk Rx architecture	$V_{RX-DIFF-PP-CC}$	2.5GT/s	0.175	N/A	1.2	V
Differential Rx peak-peak voltage for data clocked Rx architecture	$V_{RX-DIFF-PP-DC}$	2.5GT/s	0.175	N/A	1.2	V
Receiver eye time opening	T_{RX-EYE}	2.5GT/s	0.40	N/A	N/A	UI
Max time delta between median and deviation from median	$T_{RX-EYE-MEDIAN-to-MAX-JITTER}$	2.5GT/s	0.3	N/A	N/A	UI
Rx AC common mode voltage	$V_{RX-CM-AC-P}$	2.5GT/s	N/A	N/A	150	mVP
Rx package plus Si differential return loss	$RL_{RX-DIFF}$	2.5GT/s	10	N/A	N/A	dB
Common mode Rx return loss	RL_{RX-CM}	2.5GT/s	6	N/A	N/A	dB
DC differential impedance	$Z_{RX-DIFF-DC}$	2.5GT/s	80	N/A	120	Ω
Receiver DC single ended impedance	Z_{RX-DC}	2.5GT/s	40	N/A	60	Ω
Electrical Idle Detect Threshold	$V_{RX-IDLE-DET-DIFF-p-p}$	2.5GT/s	65	N/A	175	mV
Unexpected Electrical Idle Enter Detect Threshold Integration Time	$T_{RX-IDLE-DET-DIFF-ENTER-TIME}$	2.5GT/s	N/A	N/A	10	ms
Lane to Lane skew	$L_{RX-SKEW}$	2.5GT/s	N/A	N/A	20	ns

Chapter 4 Thermal Management

4.1 Overview

For reliability and operability concerns, the absolute maximum junction temperature has to be below 125°C.

4.2 Package Thermal Characteristics

Table 4-1 provides the thermal resistance characteristics for the package. The resulting simulation data for reference only, please prevail in kind test.

Table 4-1 Thermal Resistance Characteristics

Parameter	Symbol	Typical	Unit
Junction-to-ambient thermal resistance	θ_{JA}	12.39	(°C/W)
Junction-to-board thermal resistance	θ_{JB}	7.7	(°C/W)
Junction-to-case thermal resistance	θ_{JC}	0.38	(°C/W)

Note: The testing JEDEC PCB is based on 6 layers, 114.3x101.6 mm, 1.6 mm Thickness, ambient temperature is 25 °C.